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(54) **ONE-TIME-PROGRAMMABLE (OTP) IMPLEMENTATION USING MAGNETIC JUNCTIONS**

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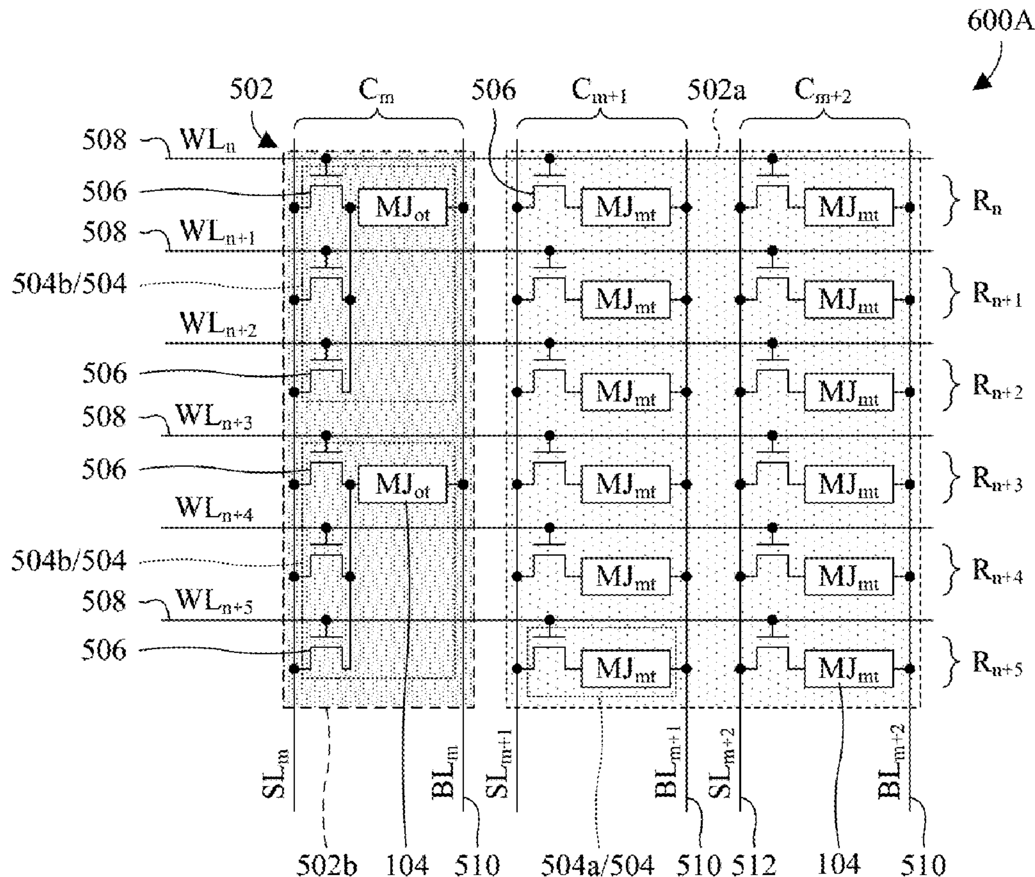
(52) **U.S. Cl.**

CPC ***G11C 17/16*** (2013.01); ***G11C 17/18*** (2013.01); ***H01L 43/12*** (2013.01); ***H01L 43/02*** (2013.01); ***H01L 27/228*** (2013.01)

(57) **ABSTRACT**

Various embodiments of the present application are directed towards a one-time-programmable (OTP) implementation using magnetic junctions. In some embodiments, an array comprises multiple magnetic junctions in multiple columns and multiple rows, and the magnetic junctions comprise a first magnetic junction and a second magnetic junction. The first and second magnetic junctions comprise individual top ferromagnetic elements and individual bottom ferromagnetic elements, and further comprise individual barrier elements between the top and bottom ferromagnetic elements. A first barrier element of the first magnetic junction electrically separates first top and bottom ferromagnetic elements of the first magnetic junction. A second barrier element of the second magnetic junction has undergone breakdown, such that it has defects defining a leakage path between second top and bottom ferromagnetic elements of the second magnetic junction. The broken-down state corresponds to a one-time programmed state and is not susceptible to high-temperature change, even at small sizes.



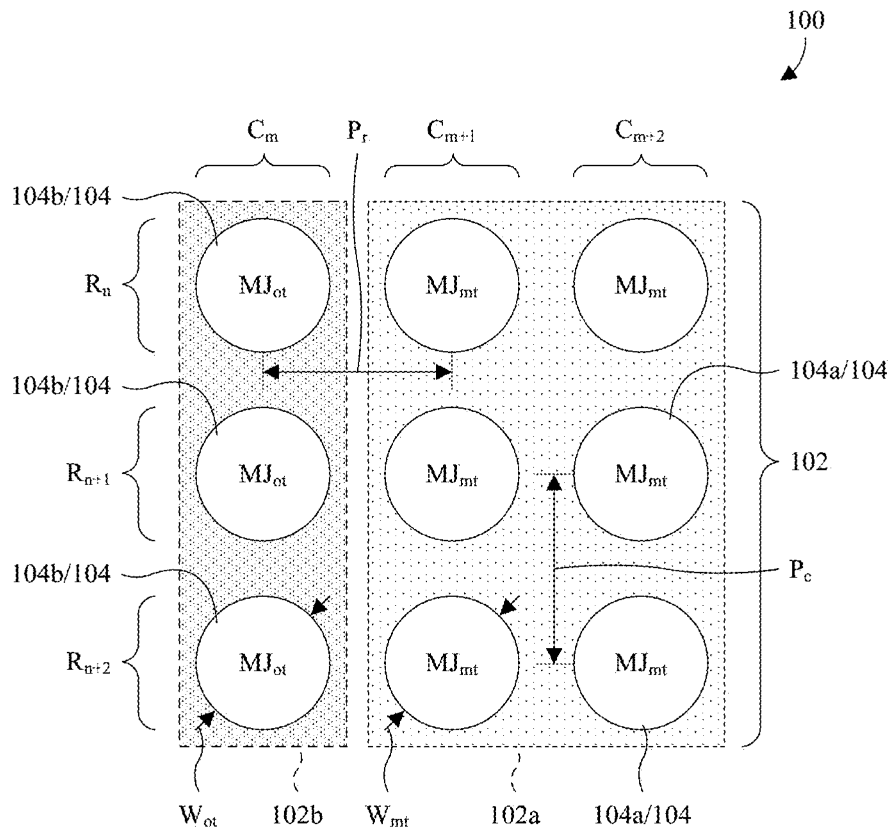


Fig. 1

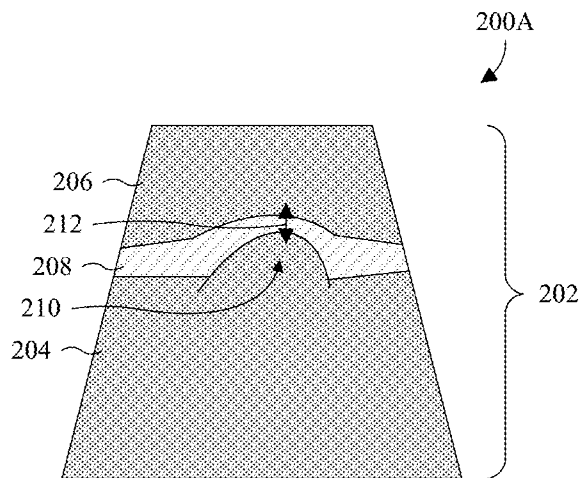


Fig. 2A

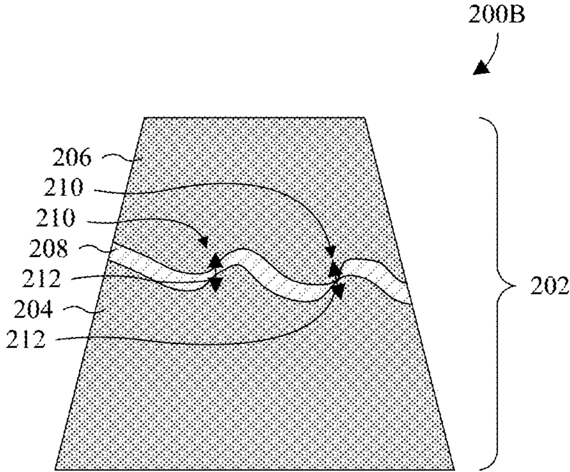


Fig. 2B

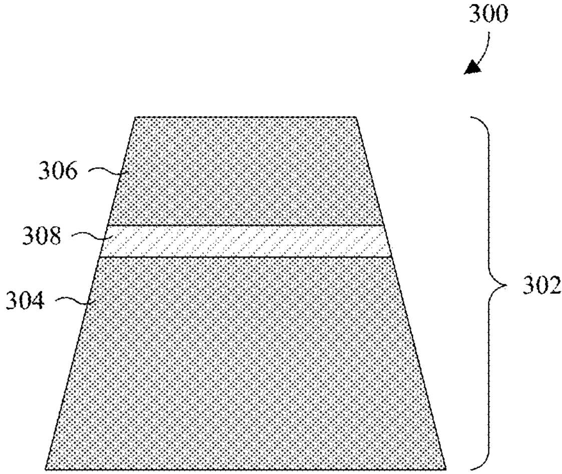


Fig. 3

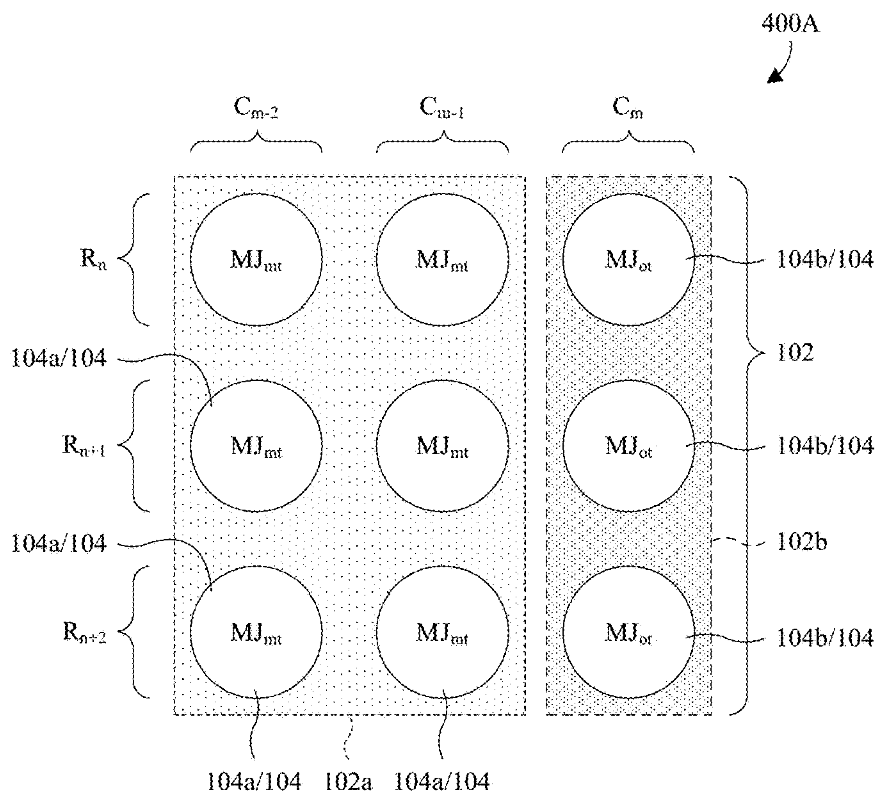


Fig. 4A

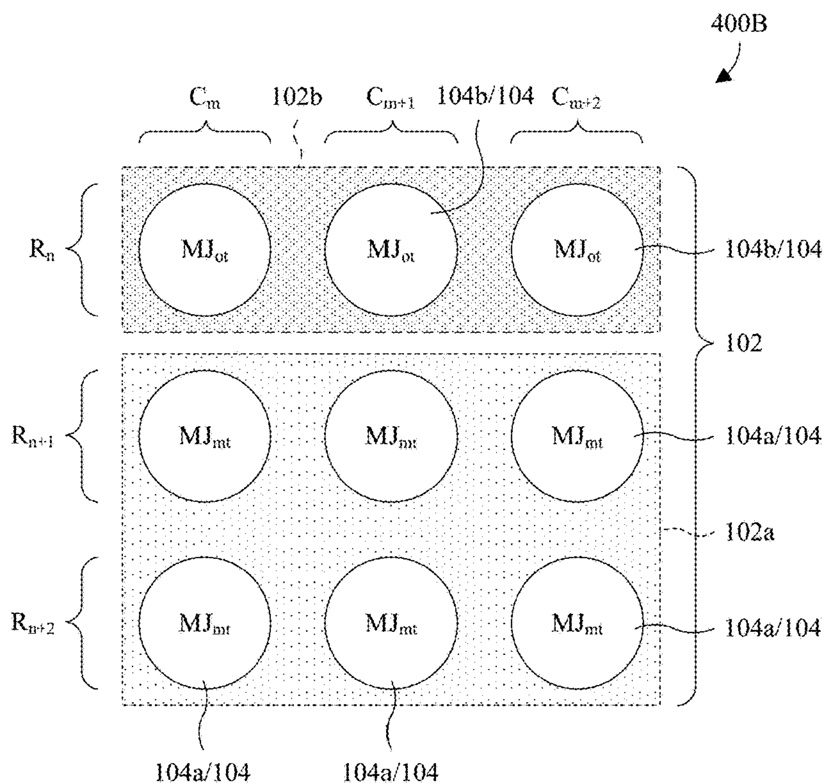


Fig. 4B

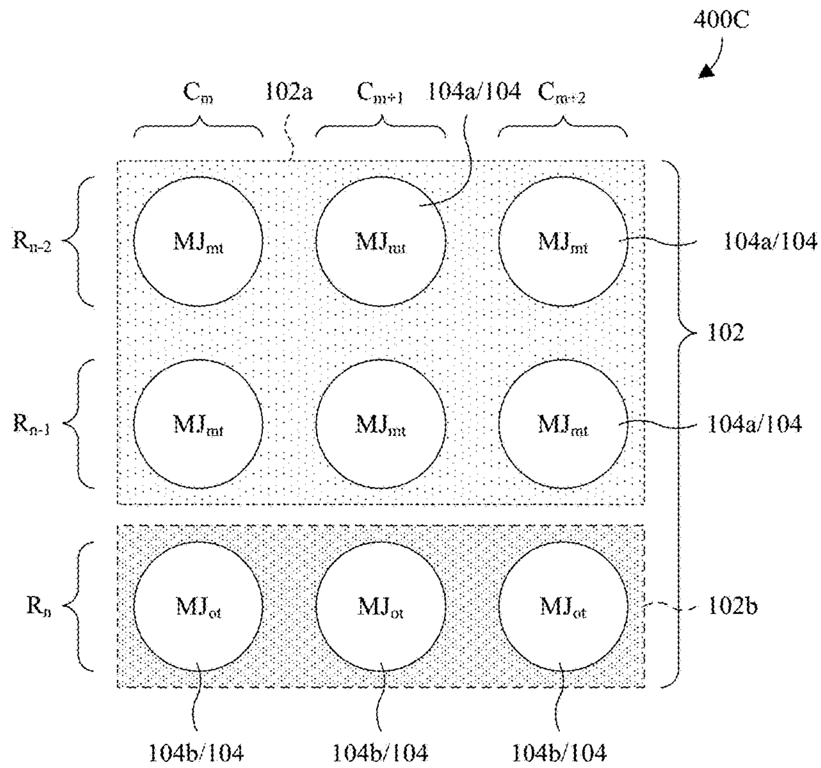


Fig. 4C

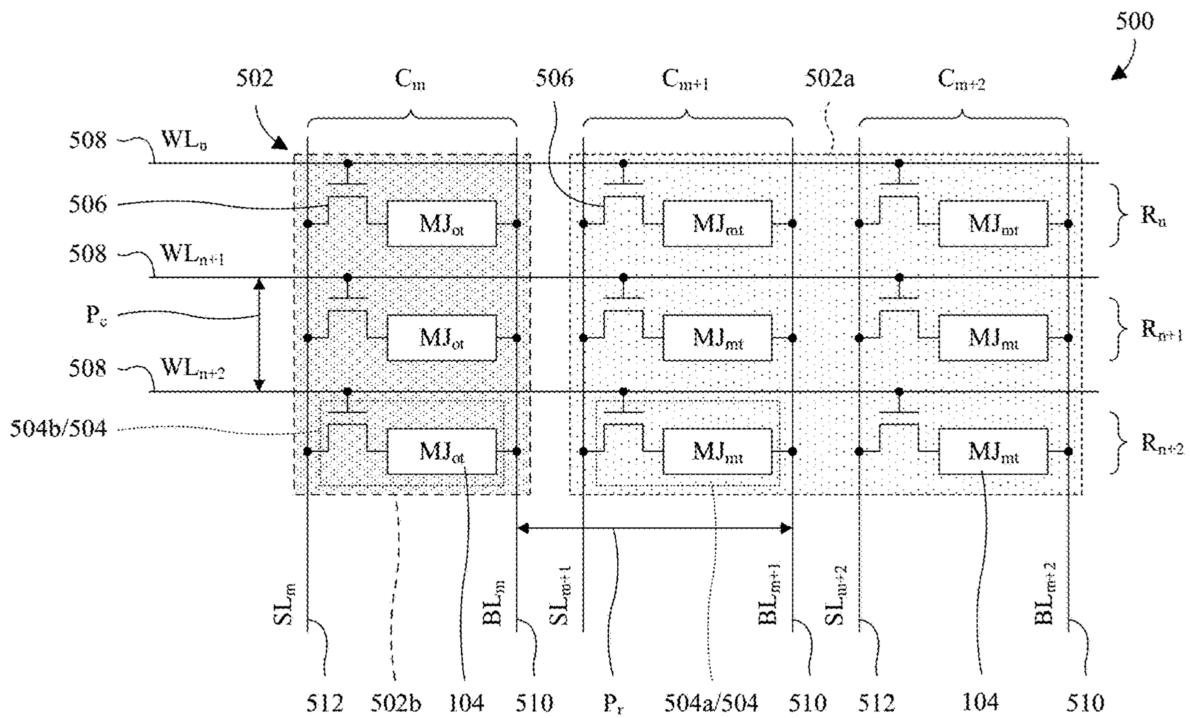


Fig. 5

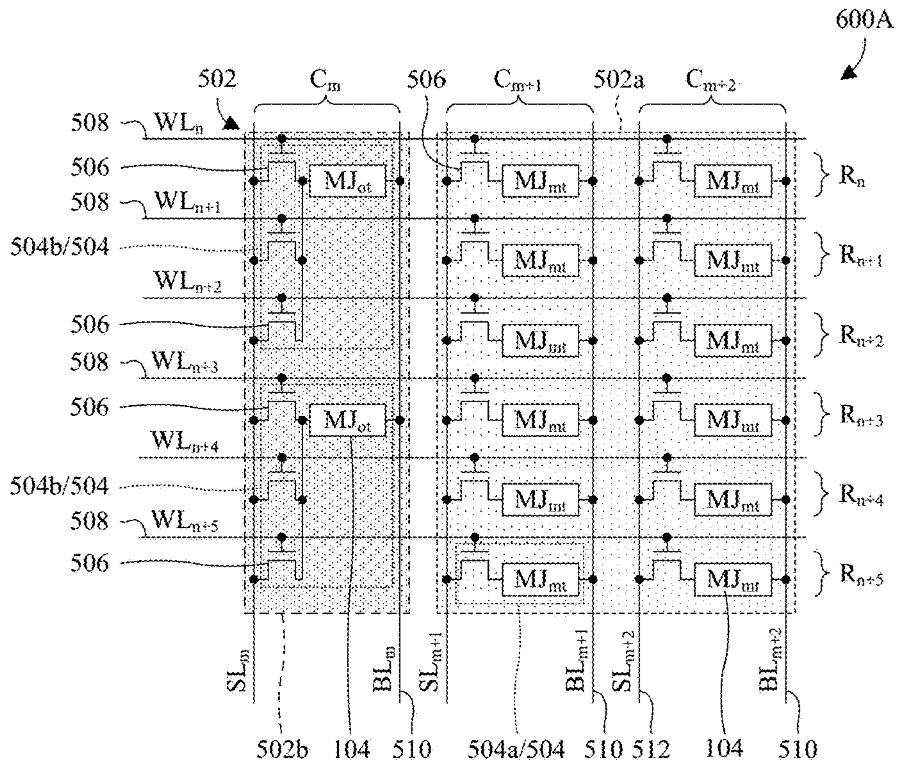


Fig. 6A

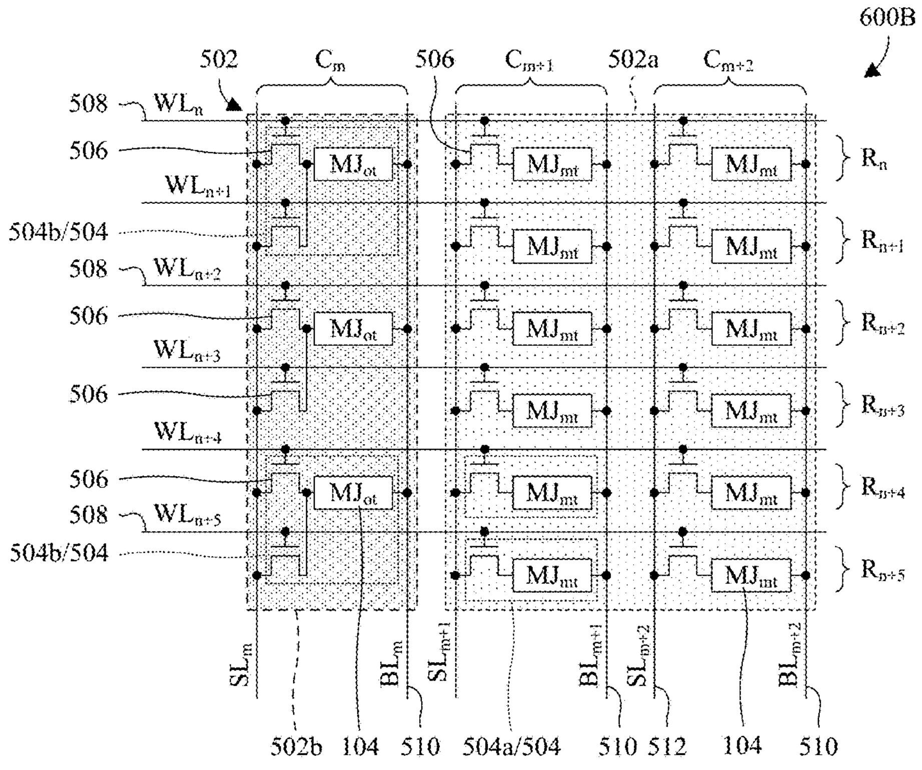


Fig. 6B

Fig. 7

Fig. 8A

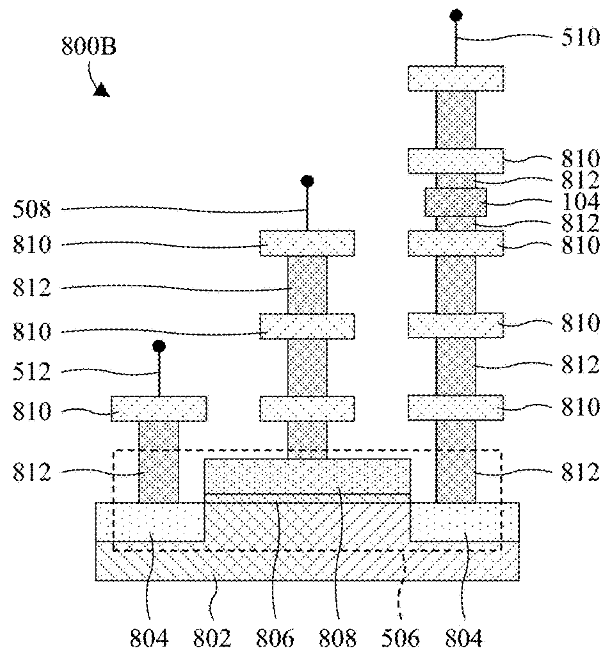


Fig. 8B

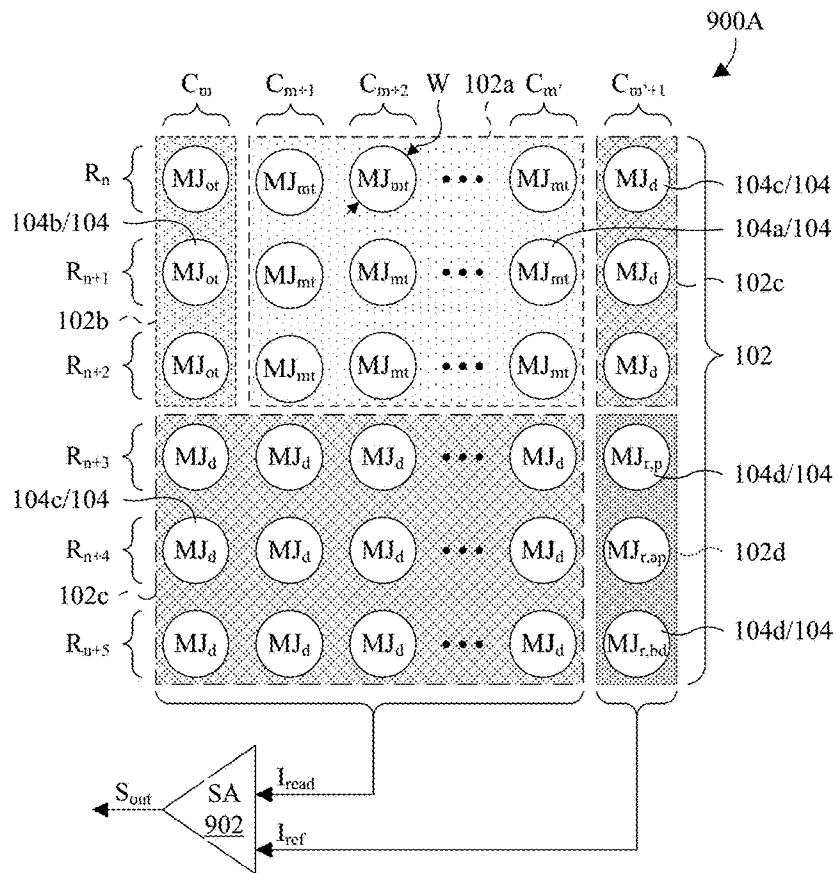


Fig. 9A

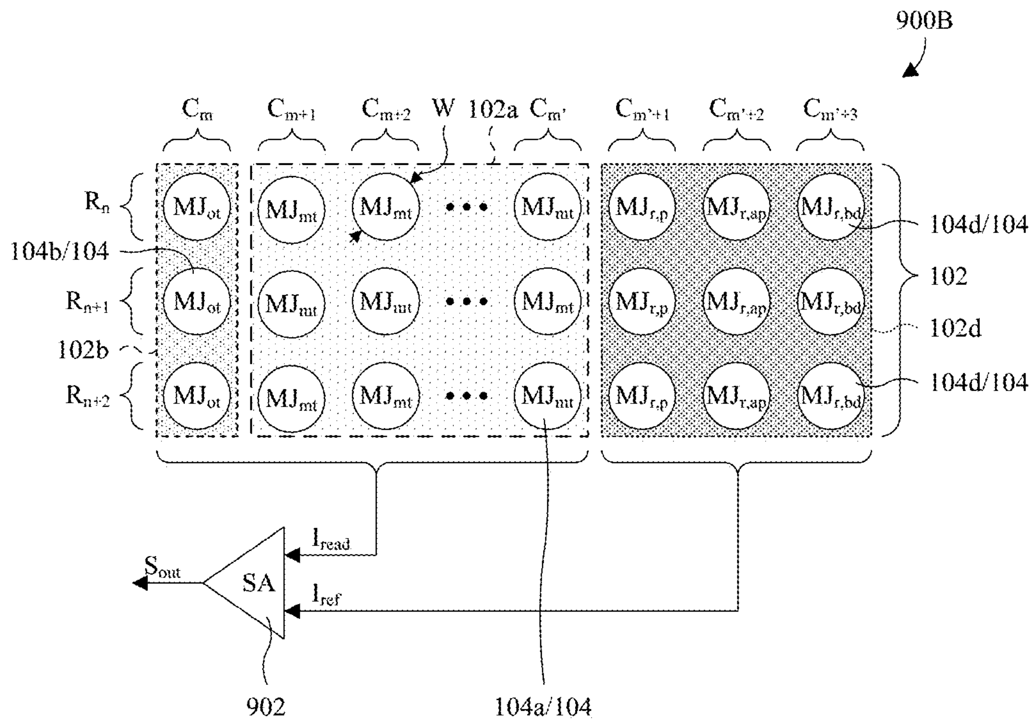


Fig. 9B

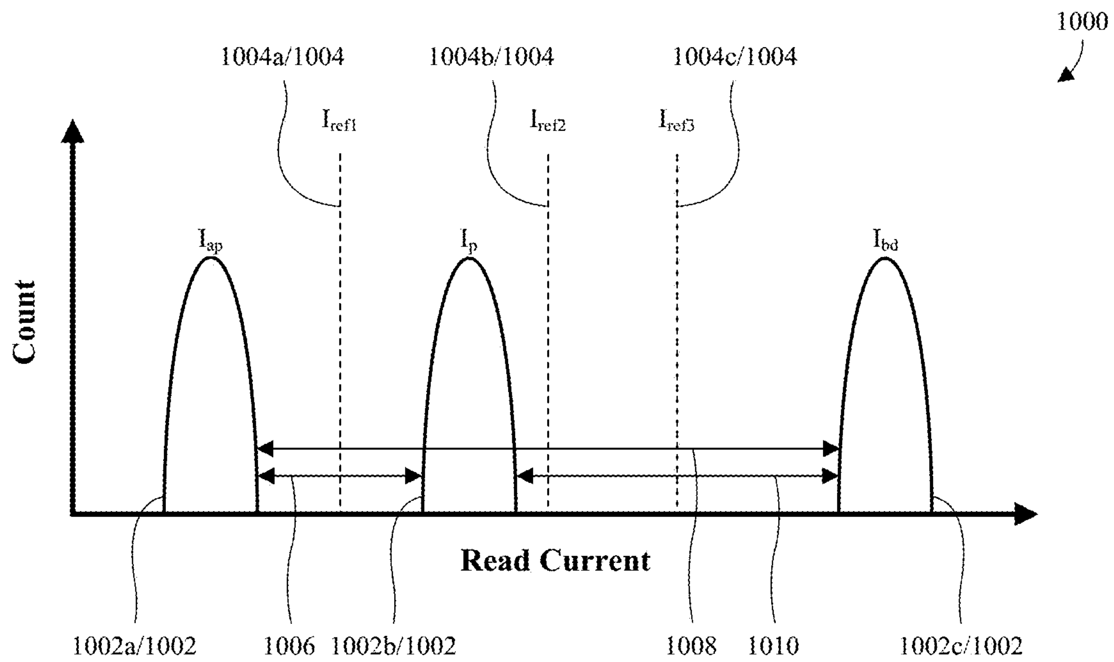


Fig. 10

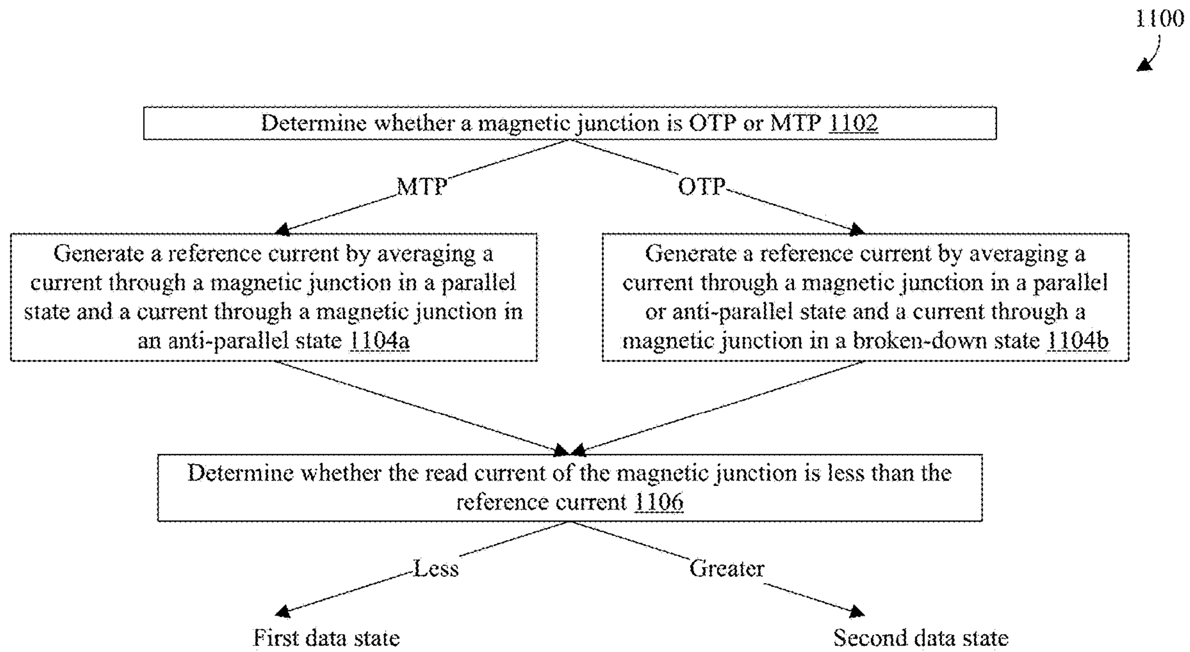


Fig. 11

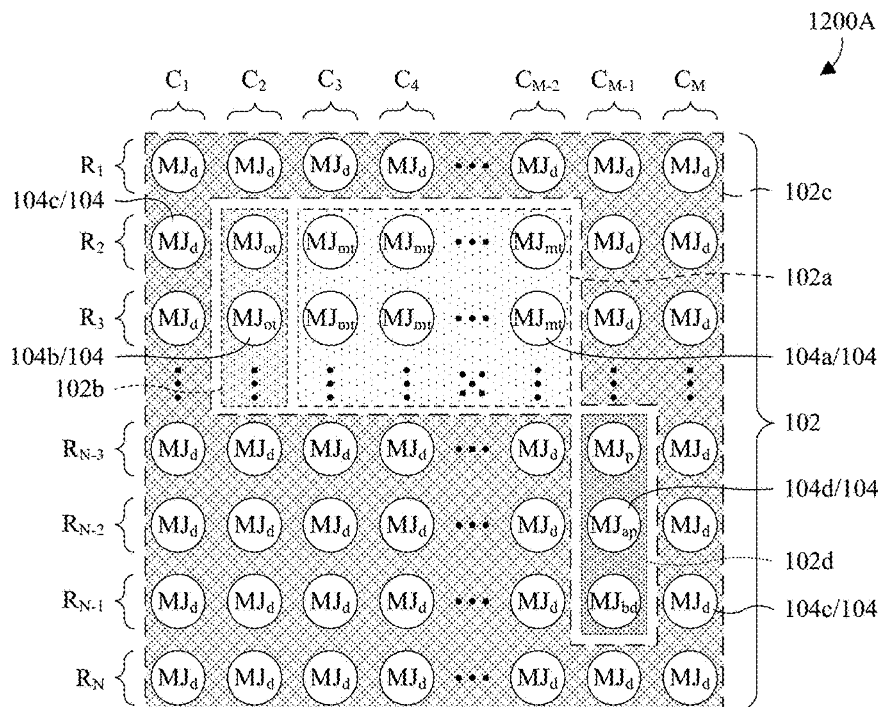


Fig. 12A

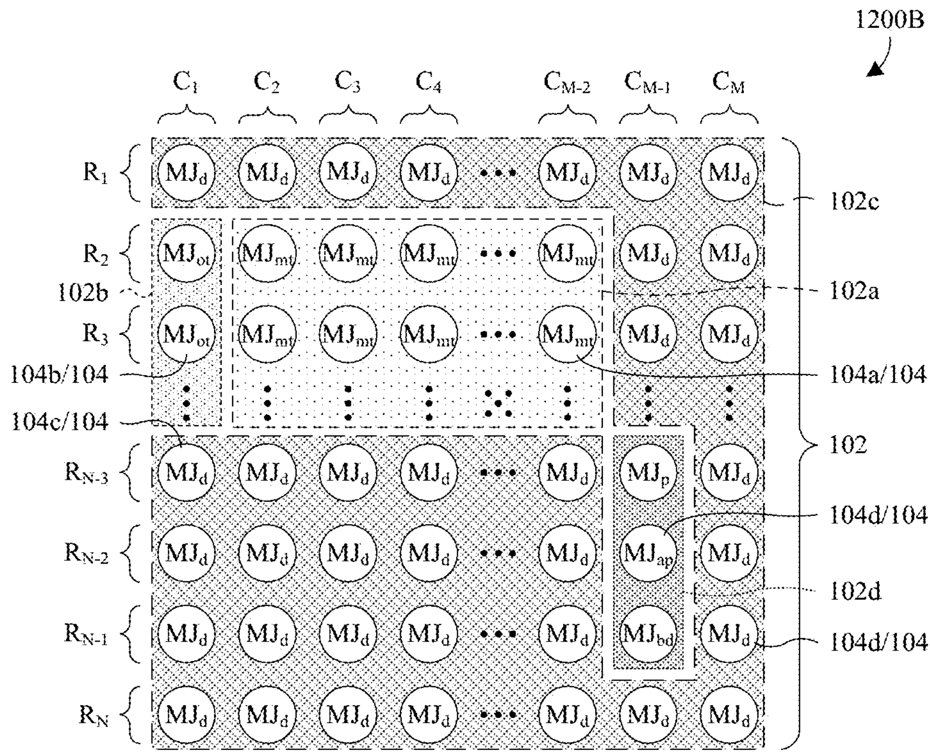


Fig. 12B

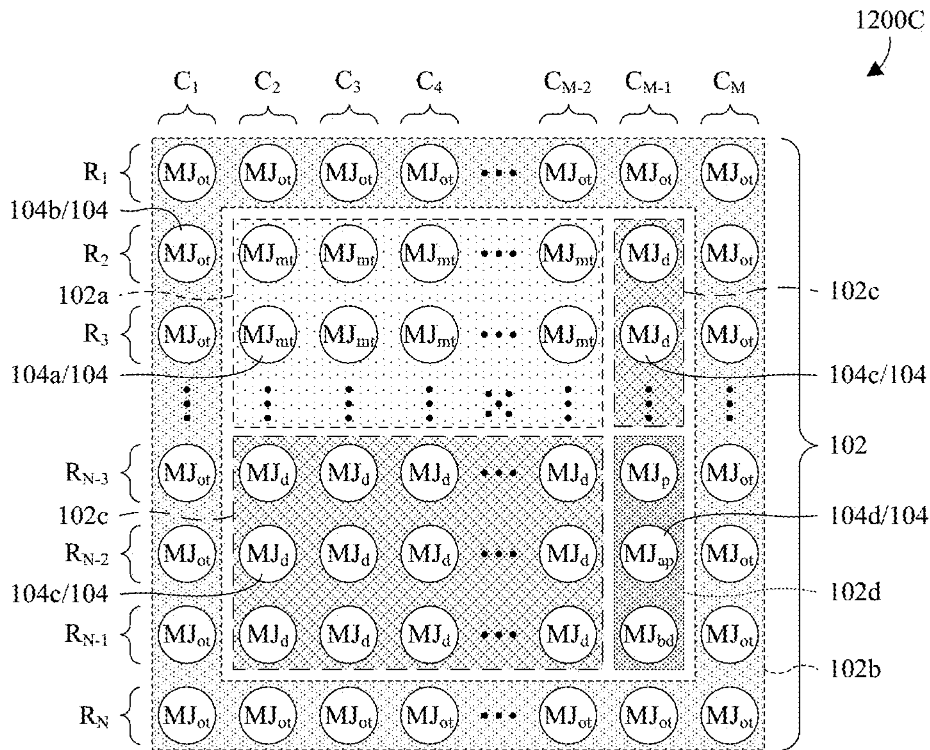


Fig. 12C

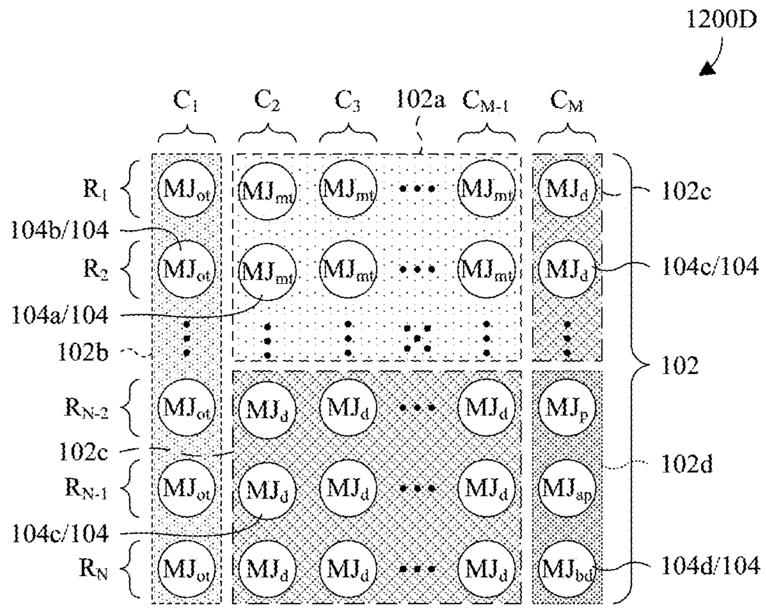


Fig. 12D

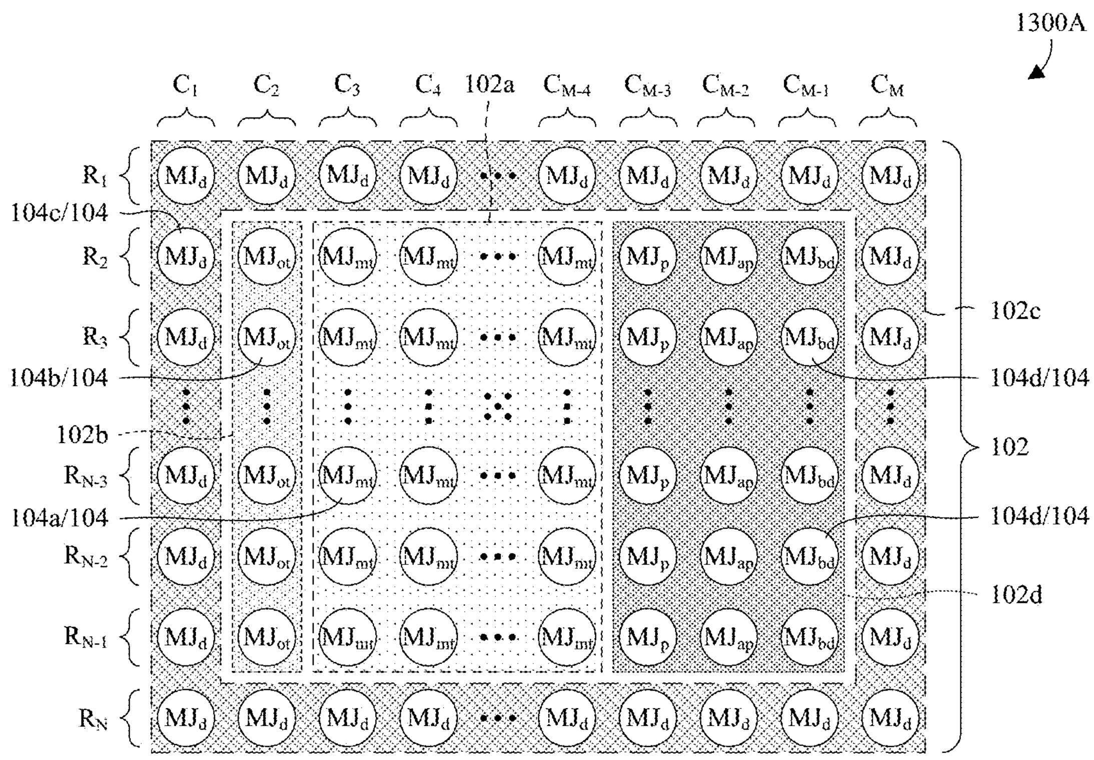


Fig. 13A

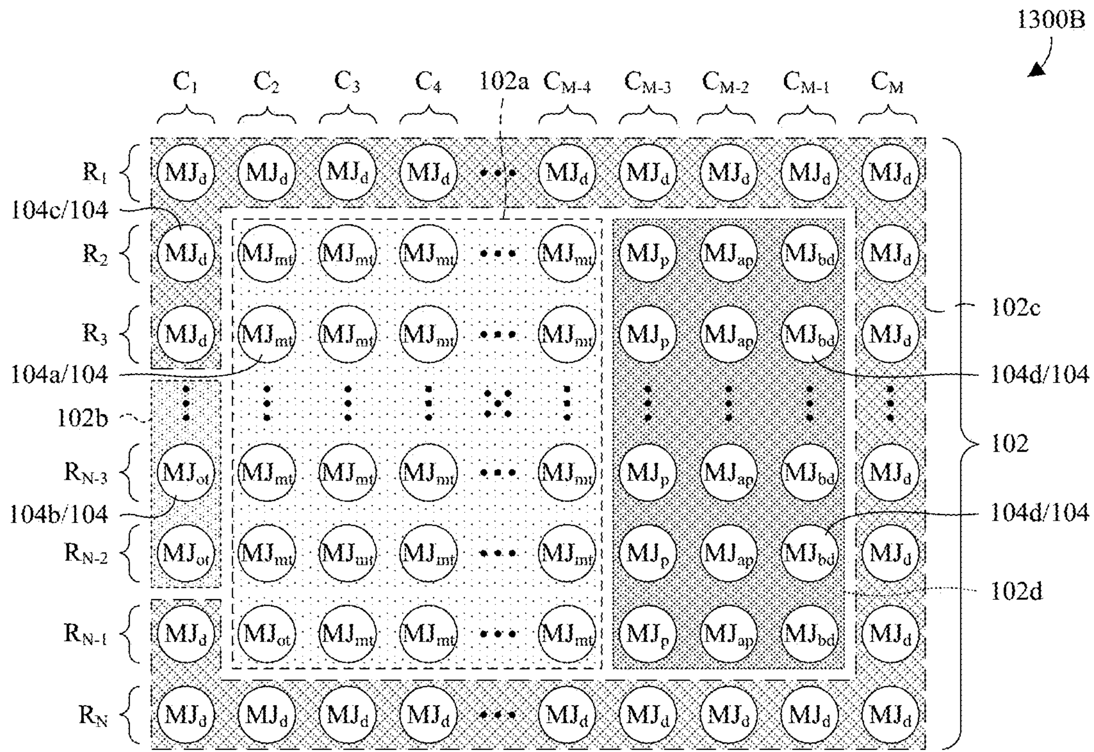


Fig. 13B

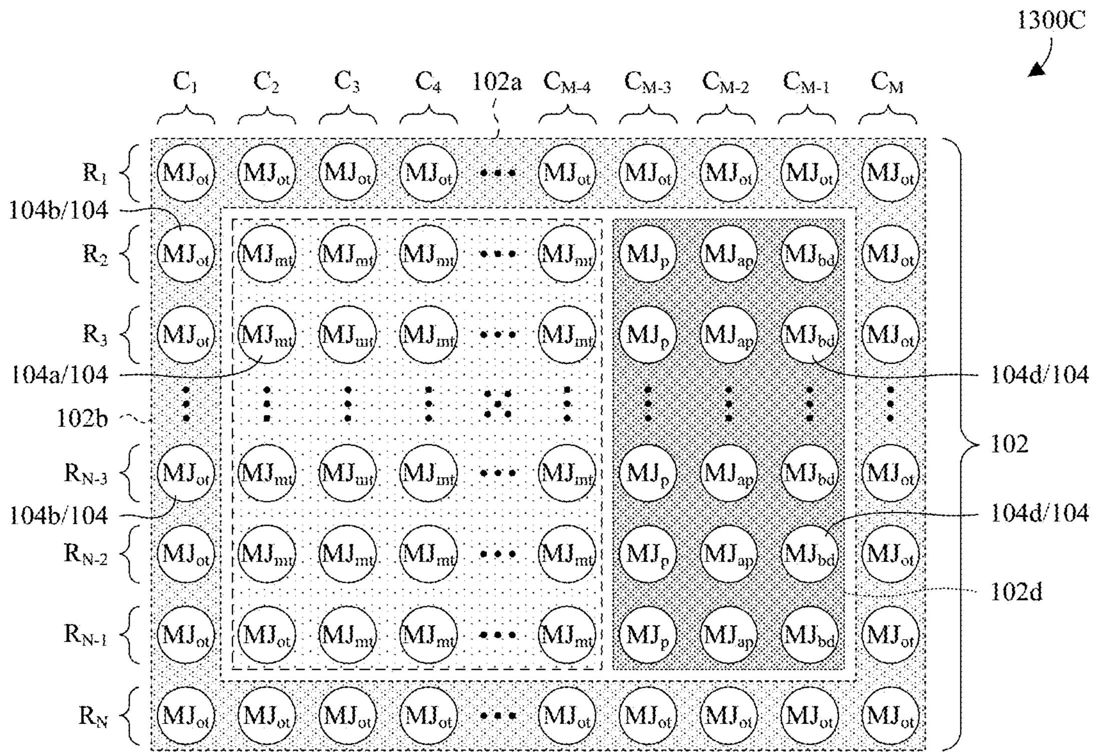


Fig. 13C

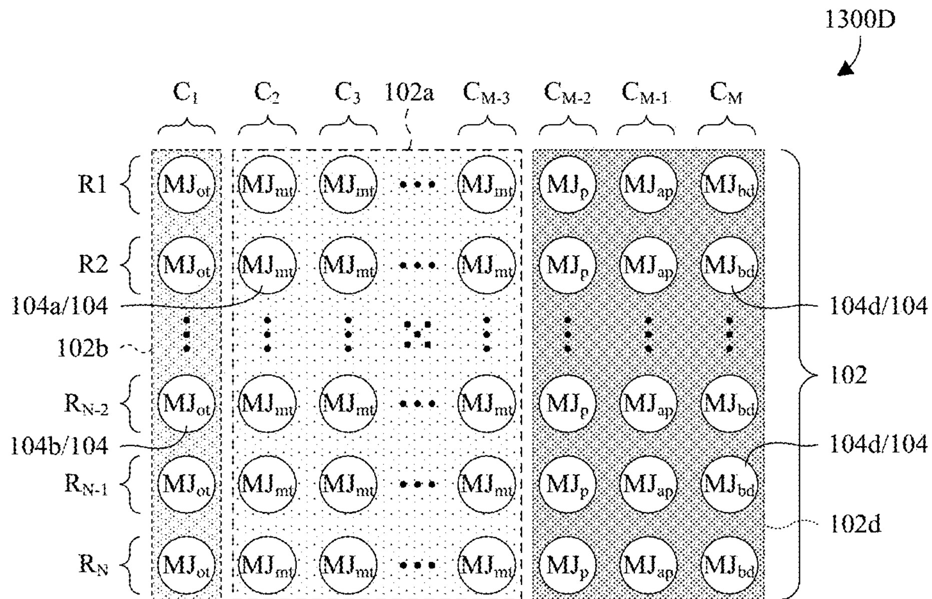


Fig. 13D

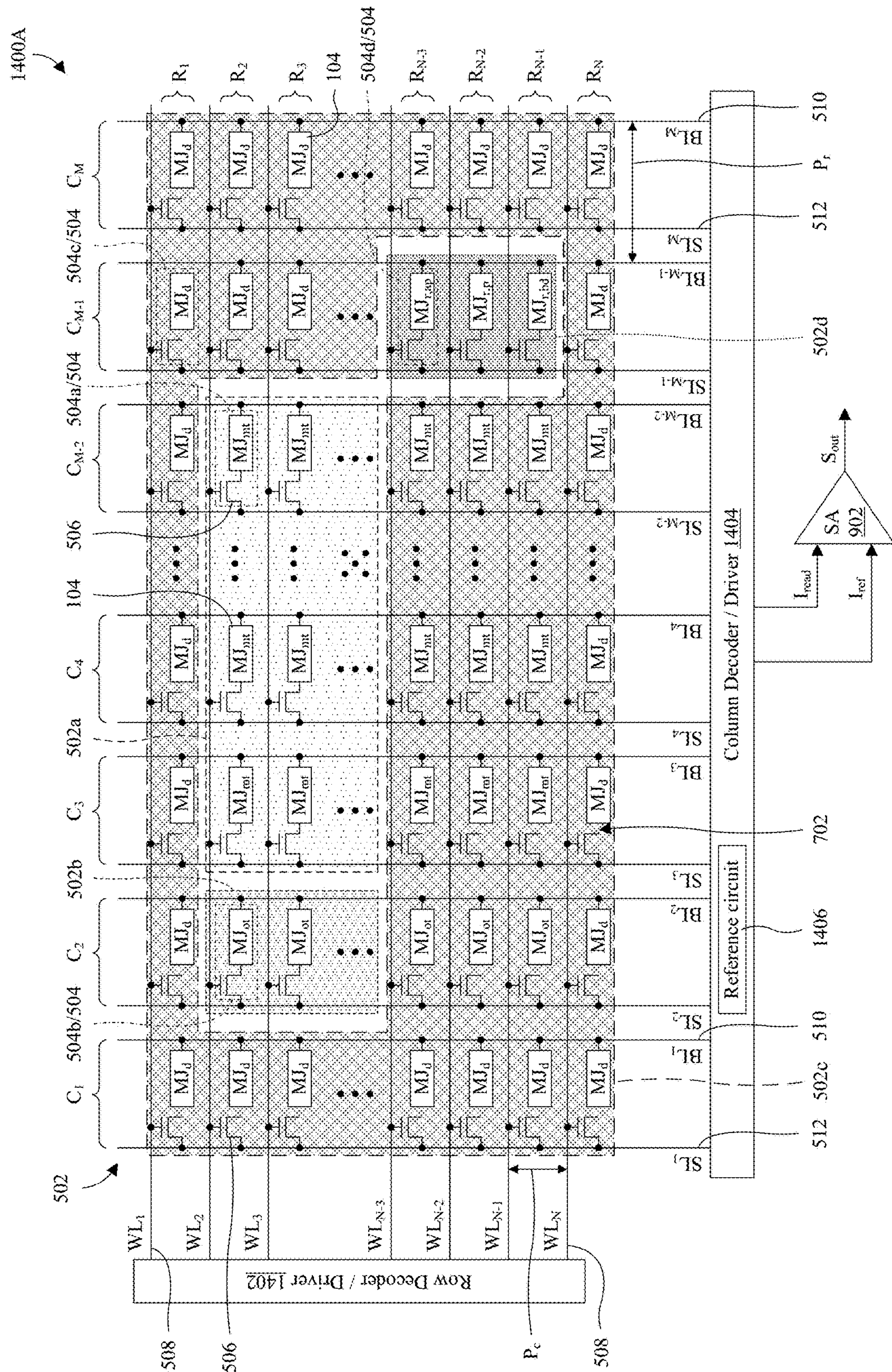


Fig. 14A

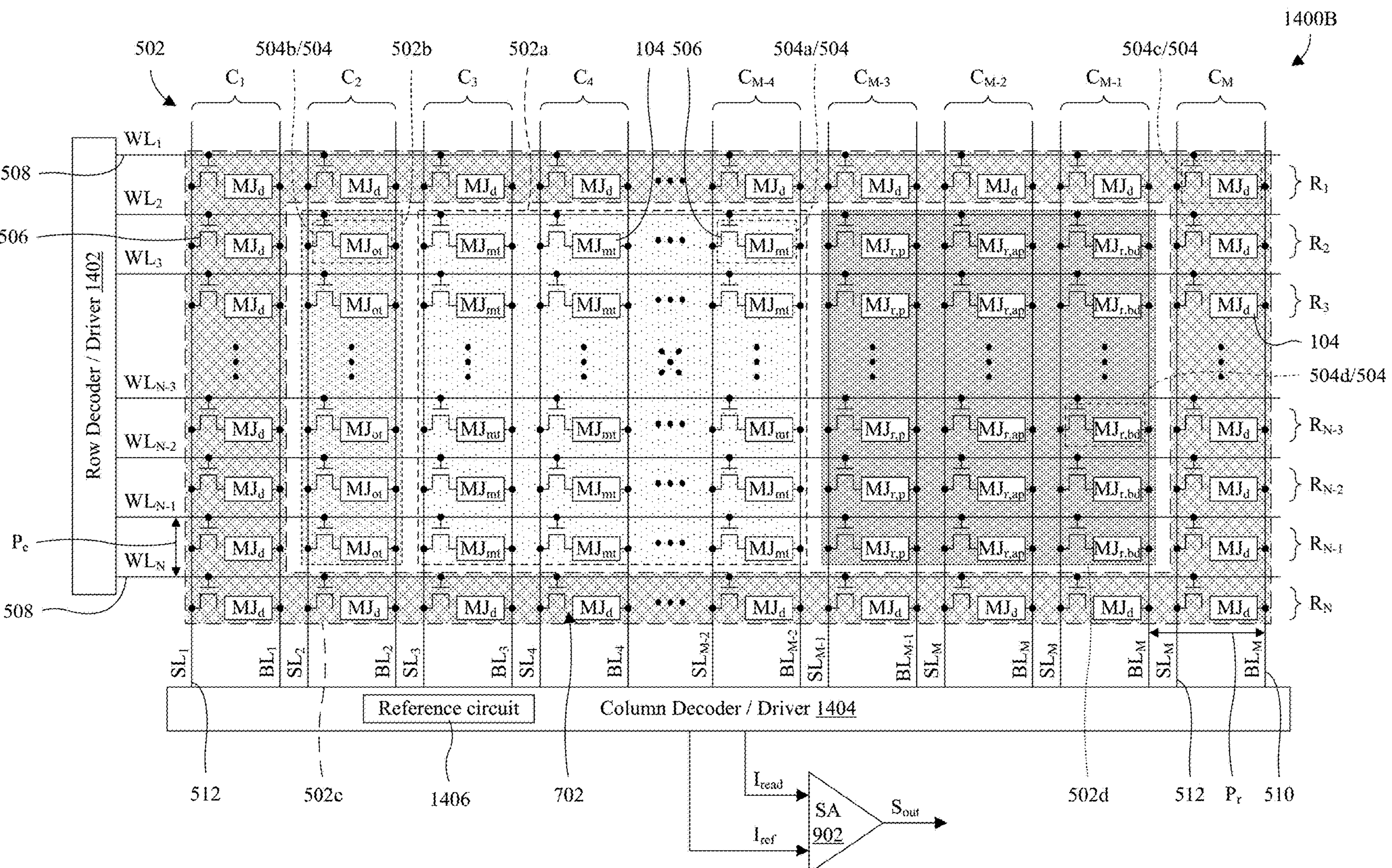


Fig. 14B

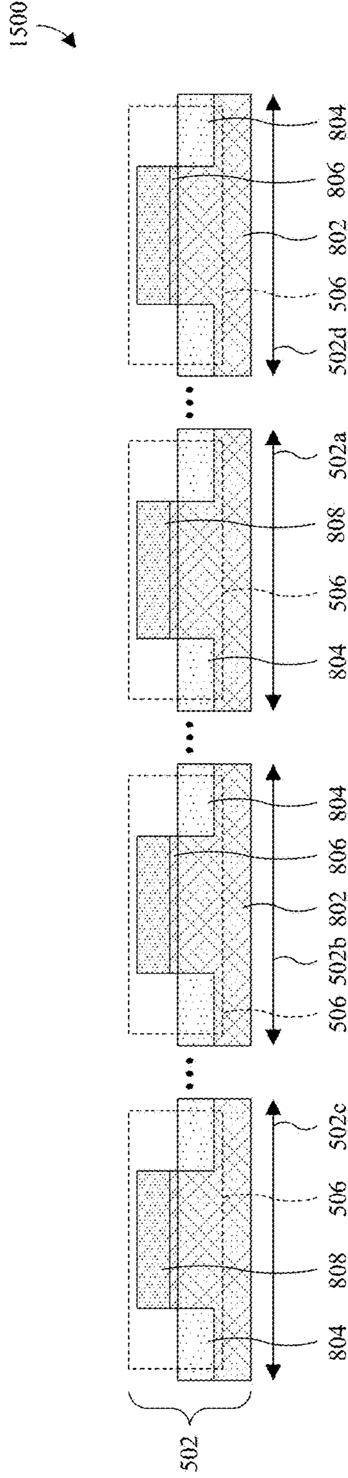


Fig. 15

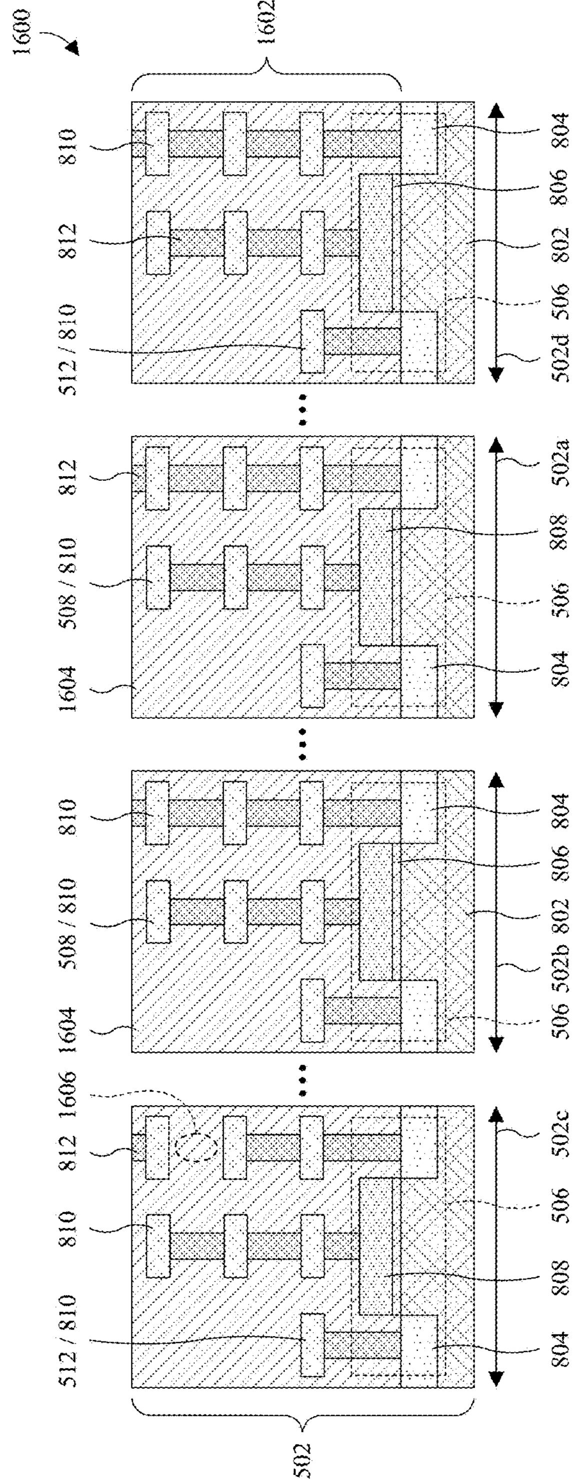


Fig. 16

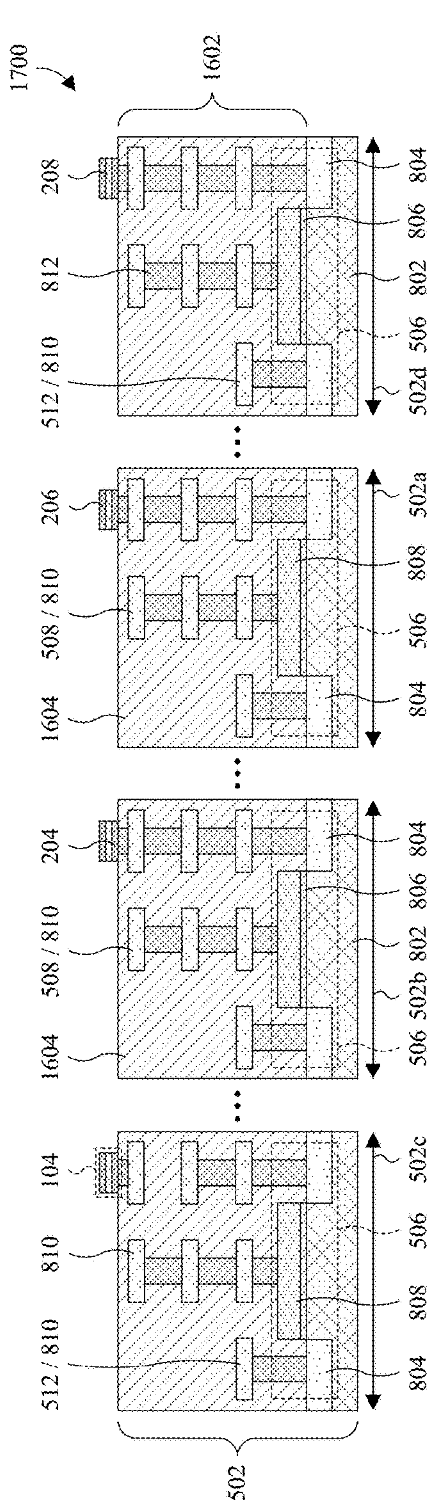


Fig. 17

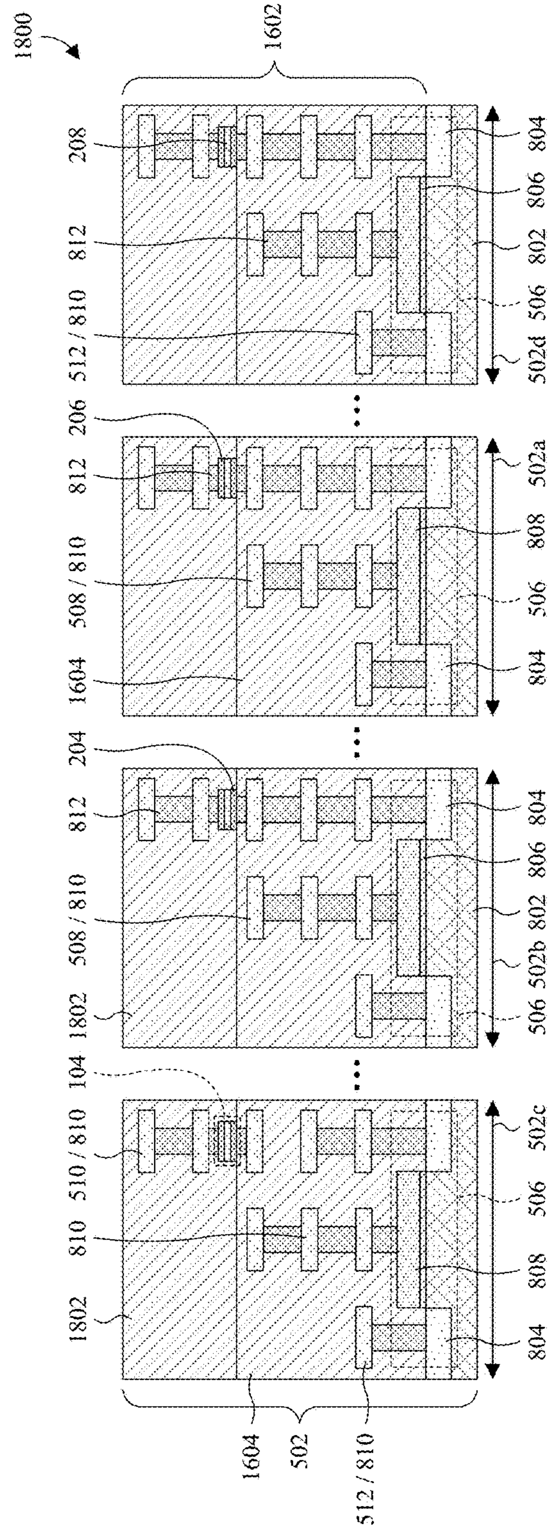


Fig. 18

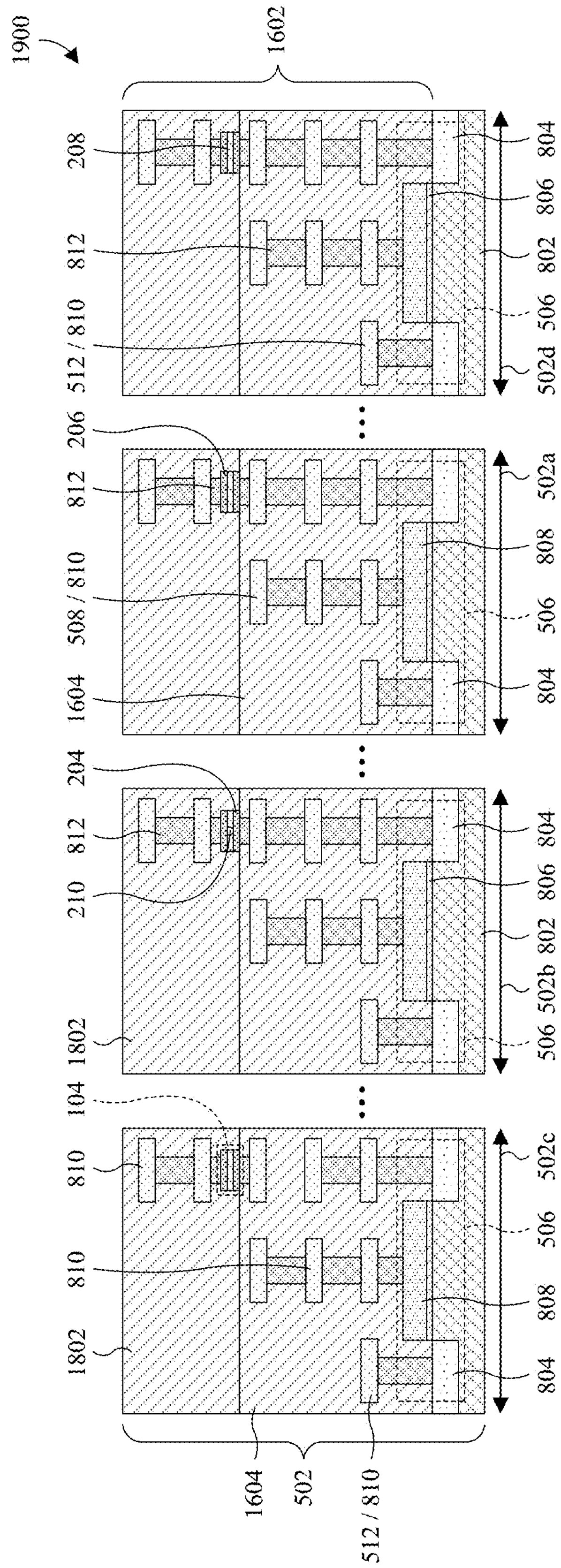


Fig. 19

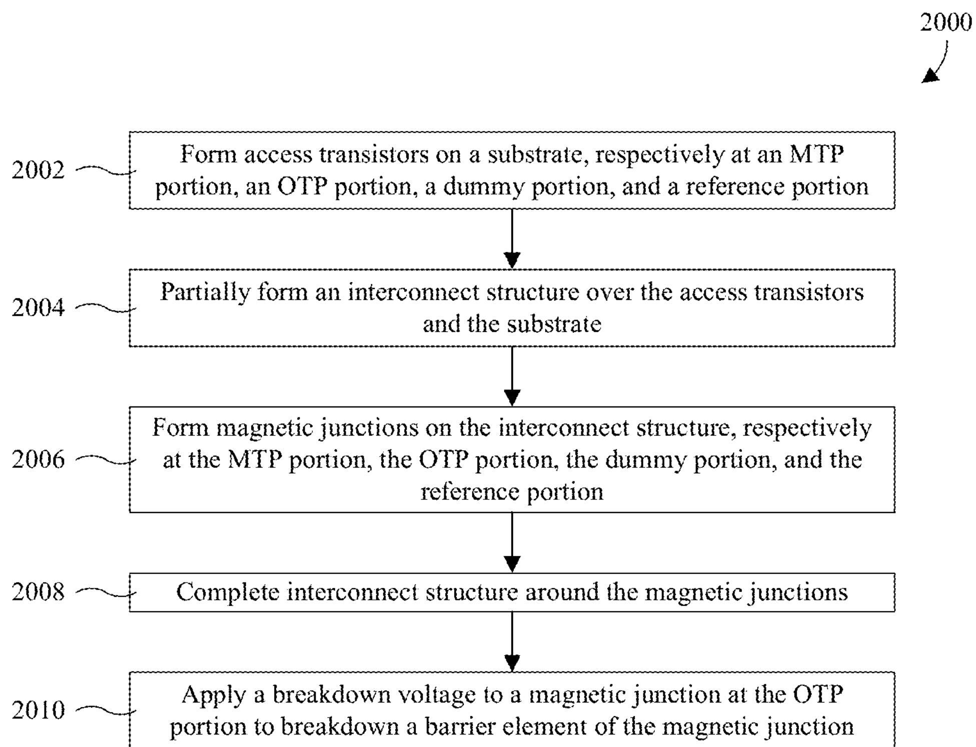


Fig. 20

ONE-TIME-PROGRAMMABLE (OTP) IMPLEMENTATION USING MAGNETIC JUNCTIONS

REFERENCE TO RELATED APPLICATION

[0001] This Application claims the benefit of U.S. Provisional Application No. 62/734,620, filed on Sep. 21, 2018, the contents of which are hereby incorporated by reference in their entirety.

BACKGROUND

[0002] Many modern electronic devices include non-volatile memory. Non-volatile memory is memory that retains data in the absence of power. Non-volatile memory includes one-time-programmable (OTP) memory and magnetoresistive random-access memory (MRAM). OTP memory is read-only memory that may only be programmed once. MRAM is a promising candidate for next generation non-volatile memory. An MRAM cell stores data using a magnetic junction, which comprises a barrier layer between two ferromagnetic elements.

BRIEF DESCRIPTION OF THE DRAWINGS

[0003] Aspects of the present disclosure are best understood from the following detailed description when read with the accompanying figures. It is noted that, in accordance with the standard practice in the industry, various features are not drawn to scale. In fact, the dimensions of the various features may be arbitrarily increased or reduced for clarity of discussion.

[0004] FIG. **1** illustrates a top layout of some embodiments of an integrated chip comprising a magnetic-junction array with a multi-time-programmable (MTP) portion and a one-time-programmable (OTP) portion.

[0005] FIGS. **2**A and **2**B illustrate cross-sectional views of various embodiments of a broken-down magnetic junction in the OTP portion of FIG. **1**.

[0006] FIG. **3** illustrates a cross-sectional view of some embodiments of an unbroken-down magnetic junction in the MTP or OTP portion FIG. **1**.

[0007] FIGS. **4**A-**4**C illustrate top layouts of various alternative embodiments of the integrated chip of FIG. **1** in which a location of the OTP portion is varied.

[0008] FIG. **5** illustrates a schematic diagram of some embodiments of an integrated chip comprising a memory array with the magnetic-junction array of FIG. **1**.

[0009] FIGS. **6**A and **6**B illustrate expanded schematic diagrams of various alternative embodiments of the integrated chip of FIG. **5** in which each memory cell comprises multiple access transistors.

[0010] FIG. **7** illustrates an expanded schematic diagram of some embodiments of the integrated chip of FIG. **5** in which an OTP portion of the memory array is at an edge of the memory array and adjoins a dummy portion of the memory array.

[0011] FIGS. **8**A and **8**B illustrate various cross-sectional views of some embodiments of a memory cell in FIG. **5**.

[0012] FIGS. **9**A and **9**B illustrate expanded top layouts of various embodiments of the integrated chip of FIG. **1** in which the magnetic-junction array further has a reference portion.

[0013] FIG. **10** illustrates a graph of some embodiments of read current distributions for the magnetic-junction array of FIGS. **9**A and **9**B and reference currents for use in FIGS. **9**A and **9**B.

[0014] FIG. **11** illustrates a block diagram of some embodiments of a process performed by the integrated chip of FIGS. **9**A and **9**B to read a state of a magnetic junction.

[0015] FIGS. **12**A-**12**D illustrate expanded top layouts of various alternative embodiments of the integrated chip of FIG. **9**A.

[0016] FIGS. **13**A-**13**D illustrate expanded top layouts of various alternative embodiments of the integrated chip of FIG. **9**B.

[0017] FIGS. **14**A and **14**B illustrate schematic diagrams of various embodiments of an integrated chip comprising a memory array respectively with the magnetic-junction arrays of FIGS. **12**A and **13**A.

[0018] FIGS. **15**-**19** illustrate a series of cross-sectional views of some embodiments of a method for forming an integrated chip comprising a memory array with an MTP portion, an OTP portion, a dummy portion, and a reference portion is provided.

[0019] FIG. **20** illustrates a block diagram of some embodiments of the method of FIGS. **15**-**19**.

DETAILED DESCRIPTION

[0020] The present disclosure provides many different embodiments, or examples, for implementing different features of this disclosure. Specific examples of components and arrangements are described below to simplify the present disclosure. These are, of course, merely examples and are not intended to be limiting. For example, the formation of a first feature over or on a second feature in the description that follows may include embodiments in which the first and second features are formed in direct contact, and may also include embodiments in which additional features may be formed between the first and second features, such that the first and second features may not be in direct contact. In addition, the present disclosure may repeat reference numerals and/or letters in the various examples. This repetition is for the purpose of simplicity and clarity and does not in itself dictate a relationship between the various embodiments and/or configurations discussed.

[0021] Further, spatially relative terms, such as "beneath," "below," "lower," "above," "upper" and the like, may be used herein for ease of description to describe one element or feature's relationship to another element(s) or feature(s) as illustrated in the figures. The spatially relative terms are intended to encompass different orientations of the device in use or operation in addition to the orientation depicted in the figures. The apparatus may be otherwise oriented (rotated 90 degrees or at other orientations) and the spatially relative descriptors used herein may likewise be interpreted accordingly.

[0022] An integrated circuit (IC) may comprise a magnetoresistive random-access memory (MRAM) array and a one-time-programmable (OTP) memory array. In some embodiments, the OTP memory array is formed separate from the MRAM array. However, this leads to high costs and increases process complexity. In other embodiments, the OTP memory array is formed as an OTP portion of the MRAM array, which is write-locked by fuses, antifuses, write circuitry, or any combination of the foregoing.

[0023] When the OTP memory array is formed as the OTP portion of the MRAM array, magnetic junctions of the MRAM array typically have the same size, regardless of whether in the OTP portion of the MRAM array or multi-time-programmable (MTP) portion of the MRAM array. Further, the magnetic junctions of the MRAM array typically have uniform or substantially uniform pitches throughout the MRAM array, regardless of whether in the OTP portion of the MRAM array or the MTP portion of the MRAM array. To form the magnetic junctions with different sizes and/or pitches leads to process complexity and reduces the process window, such that yields decrease. However, where the magnetic junctions of the MRAM array are constrained to the same size and pitches, as above, challenges arise.

[0024] Small magnetic junctions are unable to retain stored data at high temperatures. A small magnetic junction may, for example, have a width less than or equal to about 75 nanometers. The high temperatures include temperatures greater than about 100 degrees Celsius and may, for example, arise during reflow (i.e., high temperature baking) used to bond the IC to a printed circuit board (PCB). Further, while large magnetic junctions are able to retain stored data at the high temperatures, the large magnetic junctions aren't scalable and lead to large access transistors due to high current consumption. A large magnetic junction may, for example, have a width greater than about 75 nanometers. The large magnetic junctions and the large access transistors, in turn, lead to large cell pitches throughout the MRAM array.

[0025] Various embodiments of the present application are directed towards an OTP implementation using magnetic junctions. In some embodiments, an array comprises a plurality of magnetic junctions in a plurality of columns and a plurality of rows, and the plurality of magnetic junctions comprises a first magnetic junction and a second magnetic junction. The first and second magnetic junctions comprise individual top ferromagnetic elements and individual bottom ferromagnetic elements, and further comprise individual barrier elements between the top and bottom ferromagnetic elements. A first barrier element of the first magnetic junction electrically separates first top and bottom ferromagnetic elements of the first magnetic junction. Depending upon whether the first top and bottom ferromagnetic elements are in a parallel state or an anti-parallel state, the first magnetic junction is in a first data state or a second data state. A second barrier element of the second magnetic junction has undergone breakdown, and hence has defects defining a leakage path between second top and bottom ferromagnetic elements of the second magnetic junction. The defects may, for example, correspond to a hard and/or permanent breakdown of the second barrier element.

[0026] Depending upon whether the second magnetic junction is in a broken-down state (as is the case here) or an unbroken-down state, the second magnetic junction is in a first data state or a second data state. Further, when the breakdown is permanent, the second magnetic junction is OTP and not susceptible to a change in state at high temperatures (e.g., temperatures at reflow), even at small size. Hence, the broken-down state of magnetic junctions may be used to form OTP memory cells that can be scaled to small sizes and that are not susceptible to high temperatures. Further, using the broken-down state of magnetic junctions leads to a large read window, such that the OTP memory cells are less susceptible to non-uniformity. This, in turn, allows the OTP memory cells to be placed at an edge of the array with and/or in place of dummy cells. Dummy cells are unused memory cells that are typically placed at the edge of the array to offset regular memory cells from the edge since there is a high degree of non-uniformity at the edge that is detrimental to reliable operation of regular memory cells.

[0027] With reference to FIG. **1**, a top layout **100** of some embodiments of an integrated chip comprising a magnetic-junction array **102** is provided. In some embodiments, only a portion of the magnetic-junction array **102** is illustrated in the top layout **100**. The magnetic-junction array **102** comprises multiple magnetic junctions **104** distributed amongst an MTP portion **102*a*** of the magnetic-junction array **102** and an OTP portion **102*b*** of the magnetic-junction array **102**. For ease of illustration, only some of the magnetic junctions **104** are labeled **104**. In some embodiments, the OTP portion **102*b*** is at an edge of the magnetic-junction array **102**.

[0028] The magnetic junctions **104** are in a plurality of columns and a plurality of rows. The plurality of columns includes column C_m, column C_{m+1}, and column C_{m+2}, where m is an integer variable representing a column number. The plurality of rows includes row R_n, row R_{n+1}, and row R_{n+2}, where n is an integer variable representing a row number. The magnetic junctions **104** comprise individual reference elements (not shown) and individual free elements (not shown), and further comprise individual barrier elements (not shown) sandwiched between the individual reference and free elements. The magnetic junctions **104** may, for example, be or comprise magnetic tunnel junctions (MTJs), spin valves, or some other suitable magnetic junctions.

[0029] Magnetic junctions **104*a*** in the MTP portion **102*a*** (i.e., MTP magnetic junctions **104*a***) each store a bit of data, the state of which varies depending upon magnetizations of individual reference and free elements. For example, an MTP magnetic junction may have a low resistance (corresponding to a first data state) when magnetizations of individual reference and free elements are parallel and may have a high resistance (corresponding to a second data state) when magnetizations of the individual reference and free elements are anti-parallel. Further, the MTP magnetic junctions **104*a*** may each be programmed and erased multiple times by changing magnetizations of the individual free elements relative to those of the individual reference elements. Accordingly, the MTP magnetic junctions **104*a*** may be used for MRAM. For ease of illustration, only some of the MTP magnetic junctions **104*a*** are labeled **104*a***.

[0030] Magnetic junctions **104*b*** in the OTP portion **102*b*** (i.e., OTP magnetic junctions **104*b***) each store a bit of data, the state of which depends upon whether an individual barrier element has undergone breakdown. For example, an OTP magnetic junction may have a first data state when an individual barrier element has undergone breakdown and a second data state otherwise. Breakdown leads to defects in an individual barrier element, whereby leakage current may flow between an individual reference element and an individual free element. Therefore, an OTP magnetic junction has a low resistance in the first data state and a high resistance in the second data state. Further, the OTP magnetic junctions **104*b*** may each be programmed only once by breakdown of the individual barrier element. Breakdown may, for example, be permanent and/or irreversible. Accordingly, the OTP magnetic junctions **104*b*** have low resistances

once programmed and may hence be used as anti-fuses. For ease of illustration, only some of the OTP magnetic junctions **104***b* are labeled **104***b*.

[0031] By programming the OTP magnetic junctions **104***b* by breakdown, programmed states of the OTP magnetic junctions **104***b* may persist at high temperatures, even when the OTP magnetic junctions **104***b* are small. Accordingly, the magnetic-junction array **102** may be scaled down to small sizes and the OTP magnetic junctions **104***b* may still be used at high temperatures. The high temperatures may, for example, be other or otherwise include temperatures greater than or equal to about 100 or 125 degrees Celsius and/or may, for example, arise during reflow (i.e., high temperature baking) used to bond the integrated chip to a PCB. Other temperatures are, however, amenable. The OTP magnetic junctions **104***b* may, for example, be small when widths W_{ot} of the OTP magnetic junctions **104***b* are less than or equal to about 75 nanometers, 70 nanometers, 60 nanometers, or some other suitable values. Further, by programming the OTP magnetic junctions **104***b* by breakdown, the difference between a read current of a programmed OTP magnetic junction and a read current of an unprogrammed OTP magnetic junction is large. The large difference allows states of the OTP magnetic junctions **104***b* to be reliably sensed and may, for example, be greater than or equal to about 8 microamps and/or may, for example, be between about 8-18 microamps. Other values are, however, amenable.

[0032] By forming the magnetic-junction array **102** with both the MTP portion **102***a* and the OTP portion **102***b*, the OTP portion **102***b* may be readily expanded or contracted for different chip configurations. For example, the OTP portion **102***b* may be electrically and/or dynamically expanded or contracted. Further, by forming the magnetic-junction array **102** with both the MTP portion **102***a* and the OTP portion **102***b*, an MTP array and an OTP array may be formed simultaneously. This, in turn, reduces manufacturing costs and process complexity compared to separately forming an MTP array and an OTP array. Further yet, by forming the magnetic-junction array **102** with both the MTP portion **102***a* and the OTP portion **102***b*, chip area is reduced compared to separately forming an MTP array and an OTP array.

[0033] In some embodiments, the magnetic junctions **104** share a common size, regardless of whether in the MTP portion **102***a* or the OTP portion **102***b*. For example, the widths W_{ot} of the OTP magnetic junctions **104***b* may be the same as widths W_{mt} of the MTP magnetic junctions **104***a*. In some embodiments, a row-wise pitch P_r of the magnetic-junction array **102** is uniform throughout the magnetic-junction array **102**, regardless of whether at and/or between the MTP portion **102***a* and the OTP portion **102***b*. Similarly, in some embodiments, a column-wise pitch P_c of the magnetic-junction array **102** is uniform throughout the magnetic-junction array **102**, regardless of whether at and/or between the MTP portion **102***a* and the OTP portion **102***b*.

[0034] As the widths W_{ot} of the OTP magnetic junctions **104***b* shrink, the individual barrier elements of the OTP magnetic junctions **104***b* may be broken down with less current. Due to the reduced current, access transistors (not shown) associated with the magnetic junctions **104** may be reduced in size. Due to the reduced size of the magnetic junctions **104** and the reduced size of the access transistors, the row-wise pitch P_r and the column-wise pitch P_c may be reduced. Further, the chip area of the magnetic-junction array **102** may be reduced. Due to the reduced chip area, more units of the the integrated chip may be produced per wafer and/or the integrated chip may include more circuit components per unit area.

[0035] In some embodiments, the OTP magnetic junctions at row R_n and row R_{n+2} are in the broken-down state, and the OTP magnetic junction at row R_{n+1} is in the unbroken-down state, or vice versa. In some embodiments, the OTP magnetic junctions at row R_n and row R_{n+1} are in the broken-down state, and the OTP magnetic junction at row R_{n+2} is in the unbroken-down state, or vice versa. In some embodiments, the OTP magnetic junctions at row R_{n+1} and row R_{n+2} are in the broken-down state, and the OTP magnetic junction at row R_n is in the unbroken-down state, or vice versa. In some embodiments, the OTP magnetic junctions at rows R_n through R_{n+2} have the same state (e.g., the broken-down state or the unbroken-down state).

[0036] With reference to FIGS. **2**A and **2**B, cross-sectional views **200**A, **200**B of various embodiments of a broken-down magnetic junction **202** in FIG. **1** is provided. The broken-down magnetic junction **202** may, for example, be representative of each programmed OTP magnetic junction in FIG. **1** and/or may, for example, be an MTJ, a spin valve, or some other suitable magnetic junction. The broken-down magnetic junction **202** comprises a reference element **204**, a free element **206**, and a barrier element **208**. The barrier element **208** is non-magnetic and is sandwiched between the reference and free elements **204**, **206**. The reference and free elements **204**, **206** are ferromagnetic. Further, the reference element **204** has a fixed magnetization, whereas the free element **206** has a magnetization that is "free" to change.

[0037] The broken-down magnetic junction **202** has an abnormal structure compared to that of an unbroken-down magnetic junction. As part of the abnormal structure, the barrier element **208** comprises one or more defects **210** defining one or more leakage paths **212** from the reference element **204** to the free element **206**. The defect(s) **212** may, for example, be or comprise carrier traps, conductive filaments, some other suitable defect(s), or any combination of the foregoing in the barrier element **208**.

[0038] As illustrated by the cross-sectional view **200**A of FIG. **2**A, the barrier element **208** is missing material at a location where the reference element **204** bulges upward. Further, a leakage path **212** extends between the reference and free elements **204**, **206** at the bulge. The barrier element **208** may, for example, be missing material and/or have the leakage path **212** due to a hard breakdown. As such, a defect **210** defining the leakage path **212** may, for example, be or comprise a conductive filament in the barrier element **208**.

[0039] As illustrated by the cross-sectional view **200**B of FIG. **2**B, the barrier element **208** is twisted, thereby resulting in a non-uniform thickness. Further, leakage paths **212** extend between the reference and free elements **204**, **206** at thin regions of the barrier element **208**. The barrier element **208** may, for example, be twisted and/or have the leakage paths **212** due to a soft breakdown. As such, defects **210** defining the leakage paths **212** may, for example, be or comprise carrier traps in the barrier element **208**.

[0040] In some embodiments, the barrier element **208** is a tunnel barrier selectively allowing quantum mechanical tunneling of electrons through the barrier element **208**. For example, quantum mechanical tunneling may be allowed when the reference and free elements **204**, **206** have parallel magnetizations, and may be blocked when the reference and

free elements **204**, **206** have antiparallel magnetizations. The barrier element **208** may, for example, be or comprise an amorphous barrier, a crystalline barrier, or some other suitable insulating and/or tunnel barrier material. The amorphous barrier may be or comprise, for example, aluminum oxide (e.g., AlO_x), titanium oxide (e.g., TiO_x), or some other suitable amorphous barrier. The crystalline barrier may be or comprise manganese oxide (e.g., MgO), spinel (e.g., $MgAl_2O_4$), or some other suitable crystalline barrier. Alternatively (e.g., where the broken-down magnetic junction **202** is a spin valve), the barrier element **208** may be or comprise, for example, a non-magnetic metal or some other suitable barrier. Examples of non-magnetic metals include copper, gold, silver, aluminum, lead, tin, titanium, zinc, brass, bronze, or other suitable non-magnetic metal(s).

[0041] In some embodiments, the reference element **204** is or comprises cobalt iron (e.g., CoFe), cobalt iron boron (e.g., CoFeB), or some other suitable ferromagnetic material(s), or any combination of the foregoing. In some embodiments, the reference element **204** adjoins an antiferromagnetic element (not shown) and/or is part of or otherwise adjoins a synthetic antiferromagnetic (SAF) element (not shown). In some embodiments, the free element **206** is or comprises cobalt iron (e.g., CoFe), cobalt iron boron (e.g., CoFeB), or some other suitable ferromagnetic material(s), or any combination of the foregoing.

[0042] With reference to FIG. **3**, a cross-sectional view **300** of some embodiments of an unbroken-down magnetic junction **302** in FIG. **1** is provided. The unbroken-down magnetic junction **302** may, for example, be representative of each of the MTP magnetic junctions **104***a* in FIG. **1** and/or each un-programmed OTP magnetic junction in FIG. **1**. Further, the unbroken-down magnetic junction **302** may, for example, be an MTJ, a spin valve, or some other suitable magnetic junction. The unbroken-down magnetic junction **302** comprises a reference element **304**, a free element **306**, and a barrier element **308**. The barrier element **308** is non-magnetic and is sandwiched between the reference and free elements **304**, **306**. In contrast with the barrier element **208** in FIGS. **2**A and **2**B, the barrier element **308** is free of or substantially free of defects and has a uniform or substantially uniform thickness. The reference and free elements **304**, **306** are ferromagnetic. Further, the reference element **304** has a fixed magnetization, whereas the free element **306** has a magnetization that is "free" to change.

[0043] In some embodiments, the barrier element **308** is a tunnel barrier selectively allowing quantum mechanical tunneling of electrons through the barrier element **308**. In some embodiments, the barrier element **308** has the same or substantially the same material composition as the barrier element **208** of FIGS. **2**A and **2**B.

[0044] In some embodiments, the reference element **304** adjoins an antiferromagnetic element (not shown). In some embodiments, the reference element **304** is part of or otherwise adjoins a SAF element (not shown). In some embodiments, the reference element **304** has the same or substantially the same material composition as the reference element **204** of FIGS. **2**A and **2**B, and/or the free element **306** has the same or substantially the same material composition as the free element **306** of FIGS. **2**A and **2**B.

[0045] While FIGS. **2**A and **2**B illustrate the reference element **204** and the free element **206** as being respectively under and over the barrier element **208**, the reference element **204** and the free element **206** may alternatively be respectively over and under the barrier element **208**. Similarly, while FIG. **3** illustrate the reference element **304** and the free element **306** as being respectively under and over the barrier element **308**, the reference element **304** and the free element **306** may alternatively be respectively over and under the barrier element **308**.

[0046] With reference to FIGS. **4**A-**4**C, top layouts **400**A-**400**F of various alternative embodiments of the integrated chip of FIG. **1** are provided in which a location of the OTP portion **102***b* of the magnetic-junction array **102** is varied. As illustrated by the top layout **400**A of FIG. **4**A, the OTP portion **102***b* is on a right side of the MTP portion **102***a*. As illustrated by the top layout **400**B of FIG. **4**B, the OTP portion **102***b* is over the MTP portion **102***a*. As illustrated by the top layout **400**C of FIG. **4**C, the OTP portion **102***b* is below the MTP portion **102***a*.

[0047] With reference to FIG. **5**, a schematic diagram **500** of some embodiments an integrated chip comprising a memory array **502** with the magnetic-junction array **102** of FIG. **1** is provided. In some embodiments, only a portion of the memory array **502** is illustrate. The memory array **502** comprises multiple memory cells **504** distributed amongst an MTP portion **502***a* of the memory array **502** and an OTP portion **502***b* of the memory array **502**. For ease of illustration, only some of the memory cells **504** are labeled **504**.

[0048] The memory cells **504** are in a plurality of columns and a plurality of rows. The plurality of columns includes column C_m, column C_{m+1}, and column C_{m+2}, where m is an integer variable representing a column number. The plurality of rows includes row R_n, row R_{n+1}, and row R_{n+2}, where n is an integer variable representing a row number. The memory cells **504** comprise individual access transistors **506** and individual magnetic junctions **104**. For ease of illustration, only some of the access transistors **506** are labeled **506** and only some of the magnetic junctions **104** are labeled **104**. The magnetic junctions **104** have variable resistances representing bits of data. The magnetic junctions **104** may, for example, be MTJs, spin valves, or some other suitable magnetic junctions. The access transistors **506** may, for example, be metal-oxide-semiconductor field-effect transistors (MOSFETs), some other suitable insulated-gate field-effect transistors (IGFETs), or some other suitable transistors.

[0049] Memory cells **504***a* in the MTP portion **502***a* (i.e., MTP memory cells **504***a*) each store a bit of data, the state of which varies depending upon magnetizations of an individual magnetic junction MJ_{mt}. For ease of illustration, only one of the MTP memory cells **504***a* is individually labeled **504***a*. Individual magnetic junctions MJ_{mt} of the MTP memory cells **504***a* may, for example, be as the MTP magnetic junctions **104***a* are described with regard to FIG. **1**, and/or as the unbroken-down magnetic junction **302** is illustrated and described in FIG. **3**. In some embodiments, the MTP portion **502***a* of the memory array **502** comprises the MTP portion **102***a* of the magnetic-junction array **102** in FIG. **1**.

[0050] Memory cells **504***b* in the OTP portion **502***b* (i.e., OTP memory cells **504***b*) each store a bit of data, the state of which varies depending upon whether an individual magnetic junction MJ_{ot} has undergone breakdown. For ease of illustration, only one of the OTP memory cells **504***b* is individually labeled **504***b*. Individual magnetic junctions MJ_{ot} of the OTP memory cells **504***b* may, for example, be as the OTP magnetic junctions **104***b* are described with regard

to FIG. **1**. Individual magnetic junctions of the OTP memory cells **504***b* in a first data state may, for example, be as the broken-down magnetic junction **202** is illustrated and described in any one of FIGS. **2**A and **2**B, whereas Individual magnetic junctions of the OTP memory cells **504***b* in a second data state may, for example, be as the unbroken-down magnetic junction **302** is illustrated and described in FIG. **3**. In some embodiments, the OTP portion **502***b* of the memory array **502** comprises the OTP portion **102***b* of the magnetic-junction array **102** in FIG. **1**.

[0051] A set of word lines **508** facilitates selection of the memory cells **504** on a row-by-row basis, whereas a set of bit lines **510** and a set of source lines **512** facilitate reading from and/or writing to selected memory cells on a column-by-column basis. For ease of illustration, only some of the bit lines **510** are labeled **510** and only some of the source lines **512** are labeled **512**. The word lines **508** extend laterally along corresponding rows of the memory array **502** and electrically couple with gates of access transistors in the corresponding rows. The bit lines **510** extend laterally along corresponding columns of the memory array **502** and electrically couple with magnetic junctions in the corresponding columns. The source lines **512** extend laterally along corresponding columns of the memory array **502** and electrically couple with sources of access transistors in the corresponding columns.

[0052] In some embodiments, an OTP memory cell is programmed by biasing a corresponding bit line and a corresponding source line respectively with about 3.5V and 0V, and by further biasing a corresponding word line with about 2.4 volts. In some embodiments, an MTP memory cell is set to a parallel state by biasing a corresponding bit line and a corresponding source line respectively with about 1.8 volts and 0 volts, and by further biasing a corresponding word line with about 2.0 volts. In some embodiments, an MTP memory cells is set to an anti-parallel state by biasing a corresponding bit line and a corresponding source line respectively with about 0 volts and about 1.4 volts, and by further biasing a corresponding word line with about 2.4 volts. Other voltages may, however, be used to program an OTP memory cell and/or to set an MTP memory cell to a parallel or anti-parallel state.

[0053] In some embodiments, the memory cells **504** share a common size, regardless of whether in the MTP portion **502***a* or the OTP portion **502***b*. In some embodiments, a row-wise pitch P_r of the memory array **502** is uniform throughout the memory array **502**, regardless of whether at and/or between the MTP portion **502***a* and the OTP portion **502***b*. Similarly, in some embodiments, a column-wise pitch P_c of the memory array **502** is uniform throughout the memory array **502**, regardless of whether at and/or between the MTP portion **502***a* and the OTP portion **502***b*. The row-wise pitch P_r may, for example, be 260 nanometers or less, and/or the column-wise pitch P_c may, for example, be 220 nanometers or less, or vice versa. Other values for the row-wise pitch P_r and/or the column-wise pitch P_c is/are, however, amenable.

[0054] As the widths of the OTP magnetic junctions M_{ot} shrink (see, e.g., W_{ot} in FIG. **1**), the individual barrier elements of the OTP magnetic junctions M_{ot} may be broken down with less current. Due to the reduced current, the access transistors **506** associated with the magnetic junctions **104** may be reduced in size. Due to the reduced size of the magnetic junctions **104** and the reduced size of the access transistors **506**, the row-wise pitch P_r and the column-wise pitch P_c may be reduced. Further, the chip area of the memory array **502** may be reduced. Due to the reduce chip area, more units of the integrated chip may be produced per wafer and/or the integrated chip may include more circuit components per unit area.

[0055] With reference to FIGS. **6**A and **6**B, expanded schematic diagrams **600**A, **600**B of various alternative embodiments of the integrated chip of FIG. **5** are provided in which the OTP memory cells **504***b* each comprises multiple access transistors **506**. For example, as illustrated by the schematic diagram **600**A of FIG. **6**A, the OTP memory cells **504***b* may each have three access transistors. As another example, as illustrated by the schematic diagram **600**B of FIG. **6**B, the OTP memory cells **504***b* may each have two access transistors. As yet another example, the OTP memory cells **504***b* may each have four or more access transistors.

[0056] The multiple access transistors of an OTP memory cell are electrically coupled in parallel and span multiple rows. The multiple access transistors of an OTP memory cell enable more current to be driven through a magnetic junction of the OTP memory cell than if the OTP memory cell had only one access transistor. Programming a magnetic junction of an OTP memory cell may depend upon this increased current since programming is achieved by breakdown of the magnetic junction and such breakdown depends upon high current.

[0057] With reference to FIG. **7**, an expanded schematic diagram **700** of some alternative embodiments of the integrated chip of FIG. **5** is provided in which the OTP portion **502***b* is at an edge of the memory array **502** and adjoins a dummy portion **502***c* of the memory array **502**. For example, the OTP portion **502***b* and the dummy portion **502***c* may both be at column C_1 of the memory array **502**. Memory cells **504***c* in the dummy portion **502***c* (i.e., dummy memory cells **504***c*) are unused memory cells typically having poor uniformity. In some embodiments, the dummy memory cells **504***c* have the same structure as the MTP memory cells **504***a*. In other embodiments, the dummy memory cells **504***c* have magnetic junctions and access transistors that are electrically separated, as denoted by gaps **702**. For ease of illustration, only one of the dummy memory cells **504***c* is labeled **504***c* and only one of the gaps **702** is labeled **702**.

[0058] Memory cells at the edge of the memory array **502** suffer from non-uniformity due to a large change in feature density at the edge of the memory array **502**. The large change in feature density causes non-uniformity in processes used to form the memory cells at the edge of the memory array **502**, which causes the non-uniformity in the memory cells. For example, the large change in feature density may lead to thickness non-uniformity in material depositions, non-uniform chemical-mechanical planarization (CMP), non-uniform photolithography, and other non-uniformity in manufacturing processes. Hence, the dummy portion **502***c* serves as a buffer to prevent non-uniformity with memory cells offset from the edge of the memory array **502**, such as, for example, the MTP memory cells **504***a*.

[0059] The read and write windows for MTP memory cells **504***a* are relatively small compared to the read and write windows for the OTP memory cells **504***b*. Hence, the MTP memory cells **504***a* are more sensitive to non-uniformity than the OTP memory cells **504***b* and placing the MTP memory cells **504***a* at the edge of the memory array **502** may

result in poor yields. However, since the OTP memory cells **504**b are less sensitive to non-uniformity than the MTP memory cells **504**a, good yields may still be obtained with the OTP memory cells **504**b at the edge of the memory array **502**. Hence, placing the OTP memory cells **504**b at the edge of the memory array **502** allows previously unused memory cells to be used and allows the functional density of the integrated chip to be increased. This, in turn, may reduce manufacturing costs.

[0060] While FIG. **5** is illustrated using embodiments of the magnetic-junction array **102** in FIG. **1**, it is to be appreciated that embodiments of the magnetic-junction array **102** in any one of FIGS. **4**A-**4**C may alternatively be used. Further, while FIGS. **5**, **6**A, **6**B, and **7** illustrate the OTP portion **502**b as being to the left of the MTP portion **502**a, the OTP portion **502**b may be above, below, or to the right of the MTP portion **502**a in other embodiments.

[0061] With reference to FIG. **8**A, a cross-sectional view **800**A of some embodiments of a memory cell of FIG. **5** is provided. The memory cell comprises an access transistor **506** and a magnetic junction **104**. The memory cell may, for example, be representative of each of the memory cells **504** of FIG. **5**, regardless of whether an MTP memory cell, an OTP memory cell, or some other suitable memory cell.

[0062] The access transistor **506** is on a substrate **802** and comprises pair of source/drain regions **804**, a gate dielectric layer **806**, and a gate electrode **808**. The source/drain regions **804** are in the substrate **802** and have an opposite doping type as adjoining portions of the substrate **802**. The gate dielectric layer **806** overlies the substrate **802**, and the gate electrode **808** overlies the gate dielectric layer **806**. Further, the gate dielectric layer **806** and the gate electrode **808** are sandwiched between the source/drain regions **804**. The substrate **802** may, for example, be a bulk silicon substrate, some other suitable bulk semiconductor substrate, a silicon-on-insulator (SOI) substrate, or some other suitable substrate. The access transistor **506** may, for example, be a MOSFET, an IGFET, or some other suitable transistor.

[0063] Multiple wires **810** and multiple vias **812** are alternatively stacked over the access transistor **506** to define conductive paths. For ease of illustration, only some of the wires **810** are labeled **810** and only some of the vias **812** are labeled **812**. The wires **810** and the vias **812** define a first conductive path from a first one of the source/drain regions **804** to a source line **512**, and a second conductive path from the gate electrode **808** to a word line **508**. A first ellipsis **814** along the second conductive path may, for example, represent zero or more vias and zero or more wires. Further, the wires **810** and the vias **812** define a third conductive path from a second one of the source/drain regions **804** to a bottom of the magnetic junction **104**, and a fourth conductive path from a top of the magnetic junction **104** to a bit line **510**. A second ellipsis **816** along the third conductive path may, for example, represent one or more vias and zero or more wires. Similarly, a third ellipsis **818** along the fourth conductive path may, for example, represent zero or more vias and zero or more wires.

[0064] In some embodiments, the magnetic junction **104** is an MTJ, a spin valve, or some other suitable magnetic junction. In some embodiments, the magnetic junction **104** is as the magnetic junction **202** in either one of FIG. **2**A or **2**B is illustrated and described. For example, where the memory cell is an OTP memory cell that is programmed, the magnetic junction **104** may be as the magnetic junction **202** in either one of FIG. **2**A or **2**B is illustrated and described. In some embodiments, the magnetic junction **104** is as the magnetic junction **302** in FIG. **3** is illustrated and described. For example, where the memory cell is an OTP memory cell that is unprogrammed, the magnetic junction **104** may be as the magnetic junction **302** in FIG. **3** is illustrated and described. As another example, where the memory cell is an MTP memory cell, regardless of whether programmed or unprogrammed, the magnetic junction **104** may be as the magnetic junction **302** in FIG. **3** is illustrated and described.

[0065] With reference to FIG. **8**B, a cross-sectional view **800**B of some more detailed embodiments of the memory cell of FIG. **8**A is provided in which the first, second, and third ellipses **814**, **816**, **818** have been replaced. The first ellipsis has been replaced by a wire and a via. The second ellipsis has been replaced by a via. The third ellipsis has been replaced by a wire and a via. Accordingly, the source line **512** may, for example, be at a first metallization layer, and/or the word line **508** may, for example, be at a third metallization layer. Further, the magnetic junction **104** may, for example, be between a third metallization layer and a fourth metallization layer, and/or the bit line **510** may, for example, be at a fifth metallization layer.

[0066] With reference to FIG. **9**A, an expanded top layout **900**A of some embodiments of the integrated chip of FIG. **1** is provided in which the magnetic-junction array **102** further comprises a dummy portion **102**c and a reference portion **102**d. The dummy portion **102**c is above the reference portion **102**d in column $C_{m'+1}$ and is to the side of the reference portion **102**d in columns C_m to C_m'. C_m and C_m' are integer variables representing column numbers. Magnetic junctions **104**c in the dummy portion **102**c (i.e., dummy magnetic junctions **104**c) are unused. For ease of illustration, only some of the dummy magnetic junctions **104**c are labeled **104**c. As seen hereafter, the dummy magnetic junctions **104**c may, for example, be unused due to the layout of word lines and bit lines interconnecting the magnetic junctions **104** in a memory array. Magnetic junctions **104**d in the reference portion **102**d (i.e., reference magnetic junctions **104**d) correspond to the various states of the MTP and OTP magnetic junctions **104**a, **104**b. For ease of illustration, only some of the reference magnetic junctions **104**d are labeled **104**d.

[0067] The reference magnetic junctions **104**d comprise a reference magnetic junction $MJ_{r,p}$ with individual free and reference elements (not shown) in a parallel state, and further comprise a reference magnetic junction $MJ_{r,ap}$ with individual free and reference elements in an antiparallel state. The parallel state may, for example, correspond to a first data state of the MTP magnetic junctions **104**a, whereas the antiparallel state may, for example, correspond to a second data state of the MTP magnetic junctions **104**a. The reference magnetic junctions **104**d further comprise a reference magnetic junction $MJ_{r,bd}$ with in a broken-down state in which an individual barrier element that has undergone breakdown (e.g., hard and/or irreversible breakdown). The broken-down state may, for example, correspond to a first data state of the OTP magnetic junctions **104**b, whereas the parallel and/or antiparallel states may, for example, correspond to a second data state of the OTP magnetic junctions **104**b.

[0068] Depending upon the data state of the magnetic junctions **104**, the resistances of the magnetic junctions vary. For example, an MTP magnetic junction has a first resistance

in the parallel state and a second resistance in the anti-parallel state. As another example, an OTP magnetic has a first resistance in the broken-down state and a second resistance in the unbroken-down state. Hence, to read the data state of an individual magnetic junction, regardless of whether an OTP magnetic junction or an MTP magnetic junction, a read voltage is applied across the magnetic junction to generate a read current $I_{read.}$ The read current I_{read} is then compared to a reference current I_{ref} by a sense amplifier **902** to determine a data state of the magnetic junction. The reference current I_{ref} is chosen so the reference current I_{ref} is between the read current I_{read} at the two different states of a magnetic junction being read. Therefore, the magnetic junction is determined to be in a first data state if the read current I_{read} is less than the reference current I_{ref} and a second data state if the read current I_{read} is greater than the reference current I_{ref}.

[0069] In some embodiments, the reference current I_{ref} is the same between the MTP and OTP magnetic junctions **104***a*, **104***b*. For example, the reference current I_{ref} may be the average of the current through the parallel reference magnetic junctions $MJ_{r,p}$ and the current through the anti-parallel reference magnetic junctions $MJ_{r,ap}$. Further, in some embodiments, the broken-down reference magnetic junction $MJ_{r,bd}$ is omitted and/or unused.

[0070] Use of the same reference current I_{ref} between the OTP magnetic junctions **104***b* and the MTP magnetic junctions **104***a* is dependent upon the read window of the MTP magnetic junctions **104***a* overlapping with the read window of the OTP magnetic junctions **104***b*. A read window is the difference between read currents respectively at the two different states (e.g., parallel and anti-parallel states) of a magnetic junction **104**. Without an overlap with the read widows, there would be no value for the reference current I_{ref} that could be used to read both the MTP and OTP magnetic junctions **104***a*, **104***b*.

[0071] To ensure the read windows overlap, the OTP magnetic junctions **104***b* are restricted to the broken-down state and the anti-parallel state (an unbroken-down state). For example, during formation of the magnetic-junction array **102**, some of the OTP magnetic junctions **104***b* may be set to the anti-parallel state and a remainder of the OTP magnetic junctions **104***b* may be broken down. As seen hereafter, the restriction is because read current in the broken-downs state is greater than read current in the parallel state, which is greater than read current in the anti-parallel state. However, the restriction is difficult to enforce.

[0072] As integrated chips continue to become smaller and smaller, the magnetic junctions **104** become smaller and smaller. However, small magnetic junctions are unable to retain stored data at high temperatures. The small magnetic junctions may, for example, be magnetic junctions with widths (e.g., the width W) less than or equal to about 75 nanometers, 70 nanometers, 60 nanometers, or some other suitable values. Hence, high temperatures could cause an initial state of an unbroken-down OTP magnetic junction to switch from anti-parallel to parallel, which would result in read failure of the unbroken-down OTP magnetic junction. The high temperatures may, for example, include temperatures greater than about 100 degrees Celsius and/or may, for example, arise during reflow (i.e., high temperature baking) used to bond the integrated chip to a PCB. Other temperatures are, however, amenable.

[0073] Additionally, the reference current I_{ref} is generated from the parallel reference magnetic junctions $MJ_{r,p}$ and the anti-parallel reference magnetic junctions $MJ_{r,ap}$, such that the reference current I_{ref} would be incorrect if the parallel and anti-parallel reference magnetic junctions $MJ_{r,p}$, $MJ_{r,ap}$ had the incorrect states. Further, the parallel and anti-parallel reference magnetic junctions $MJ_{r,p}$, $MJ_{r,ap}$ are subject to changes in states at high temperatures in the same manner as described above for the unbroken-down OTP magnetic. Hence, high temperatures could change the reference current I_{ref} and result in read failure.

[0074] In other embodiments, the reference current I_{ref} is varied depending upon whether a magnetic junction being read is an OTP magnetic junction or an MTP magnetic junction. For example, the reference current I_{ref} may be the average of the current through the parallel reference magnetic junctions $MJ_{r,p}$ and the current through the anti-parallel reference magnetic junctions $MJ_{r,ap}$ when reading an MTP magnetic junction. As another example, the reference current I_{ref} may be the average of the current through the anti-parallel or parallel reference magnetic junction $MJ_{r,ap}$, $MJ_{r,p}$ and the current through the broken-down reference magnetic junctions $MJ_{r,bd}$ when reading an OTP magnetic junction.

[0075] By using an average of the current through the anti-parallel or parallel reference magnetic junction $MJ_{r,ap}$, $MJ_{r,p}$ and the current through the broken-down reference magnetic junctions $MJ_{r,bd}$ when reading an OTP magnetic junction, high-temperature read failure of the OTP magnetic junctions **104***b* may be avoided. The broken-down reference magnetic junction $MJ_{r,bd}$ is unaffected by high temperatures. Further, even if the state of the anti-parallel or parallel reference magnetic junction $MJ_{r,ap}$, MJ_{rp} changes at the high temperatures and/or an unbroken-down OTP magnetic junction changes between parallel and anti-parallel, the reference current I_{ref} remains in the read window of the unbroken-down OTP magnetic junction and reads succeed.

[0076] With reference to FIG. **9**B, a top layout **900**B of some alternative embodiments of the integrated chip of FIG. **9**A is provided in which each row of the magnetic-junction array **102** comprises three individual reference magnetic junctions **104***d*: 1) a parallel reference magnetic junction $MJ_{r,p}$; 2) an anti-parallel reference magnetic junction $MJ_{r,ap}$; and 3) a breakdown reference magnetic junction $M_{Jr,bd}$. For ease of illustration, only some of the reference magnetic junctions **104***d* are labeled **104***d*. During readout of a magnetic junction in the MTP and OTP portions **102***a*, **102***b*, the individual reference magnetic junctions in a corresponding row of the magnetic junction are used to generate the reference current I_{ref}.

[0077] With FIGS. **9**A and **9**B expand upon embodiments of the magnetic-junction array **102** of FIG. **1**, it is to be understood that FIGS. **9**A and **9**B may alternatively expand upon embodiments of the magnetic-junction array **102** of FIGS. **4**A-**4**C. For example, the OTP portion **102***b* may be shifted to the right of the MTP portion **102***a*. As another example, the OTP portion **102***b* may be shifted above or below the MTP portion **102***a*.

[0078] With reference to FIG. **10**, a graph **1000** of some embodiments of read current distributions **1002** for the magnetic-junction array **102** of FIGS. **9**A and **9**B and read currents **1004** for use in FIGS. **9**A and **9**B is provided. A horizontal axis of the graph **1000** corresponds to read

current, and a vertical axis of the graph **1000** corresponds to the number of samples (i.e., different memory cells) having a given read current.

[0079] The read current distributions **1002** include an antiparallel read current distribution **1002***a*, a parallel read current distribution **1002***b*, and a broken-down read current distribution **1002***c*. The antiparallel read current distribution **1002***a* is representative of a read current for any one of the MTP magnetic junctions **104***a* in FIGS. **9**A and **9**B when in an antiparallel state (i.e., a high resistance state). The parallel read current distribution **1002***b* is representative of a read current for any one of the MTP magnetic junctions **104***a* in FIGS. **9**A and **9**B when in a parallel state (i.e., a low resistance state). When any one of the OTP magnetic junctions **104***b* in FIGS. **9**A and **9**B is unprogrammed, the OTP memory cell may be in an antiparallel or parallel state. Hence, the antiparallel or parallel read current distribution **1002***a*, **1002***b* may be representative of a read current for any one of the OTP magnetic junctions **104***b* in FIGS. **9**A and **9**B when in an unbroken-down state (i.e., a high resistance state). The broken-down read current distribution **1002***c* is representative of a read current for any one of the OTP magnetic junctions **104***b* in FIGS. **9**A and **9**B when in a broken-down state (i.e., a low resistance state).

[0080] A first reference current **1004***a* is at a center of an MTP read window **1006** for the MTP magnetic junctions **104***a* and is used by the sense amplifier **902** of FIGS. **9**A and **9**B to determine whether an MTP magnetic junction is in a parallel state or an anti-parallel state. The first reference current **1004***a* may, for example, correspond to an average of the current through an anti-parallel reference magnetic junction $MJ_{r,ap}$ of FIGS. **9**A and **9**B and the current through a parallel reference magnetic junction $MJ_{r,p}$ of FIGS. **9**A and **9**B.

[0081] In some embodiments, the first reference current **1004***a* is also used by the sense amplifier **902** of FIGS. **9**A and **9**B to determine whether an OTP magnetic junction is in a broken-down state or an unbroken-down state since it overlaps with a first OTP read window **1008** for the OTP magnetic junctions **104***b* so long as unprogrammed OTP magnetic junctions are restricted to the anti-parallel state. However, the first reference current **1004***a* is not equidistant from the antiparallel read current distribution **1002***a* and the broken-down read current distribution **1002***c*. Rather, the first reference current **1004***a* is much closer to the antiparallel read current distribution **1002***a* than the broken-down read current distribution **1002***c*, such that read failure is more likely when an OTP magnetic junctions **104***b* is in the unbroken-down state than when in the broken-down state. Further, if unprogrammed OTP magnetic junctions are not restricted to the anti-parallel state, the OTP magnetic junctions **104***a* shift to a second OTP read window **1010**, which does not overlap with the first reference current **1004** and hence leads to read failure. As discussed above, the restriction is difficult to enforce at high temperatures.

[0082] In other embodiments, a second reference current **1004***b* or a third reference current **1004***c* are used by the sense amplifier **902** of FIGS. **9**A and **9**B to determine whether an OTP magnetic junction is in a broken-down state or an unbroken-down state. The second reference current **1004***b* is at a center of the first OTP read window **1008** and may, for example, correspond to an average of the current through an anti-parallel reference magnetic junction $MJ_{r,ap}$ of FIGS. **9**A and **9**B and the current through a broken-down reference magnetic junction $MJ_{r,bd}$ of FIGS. **9**A and **9**B. The third reference current **1004***c* is at a center of the second OTP read window **1010** and may, for example, correspond to an average of the current through a parallel reference magnetic junction $MJ_{r,p}$ of FIGS. **9**A and **9**B and the current through a broken-down reference magnetic junction $MJ_{r,bd}$ of FIGS. **9**A and **9**B. The second reference current **1004***b* and the third reference current **1004***c* both overlap with the first and second OTP read windows **1008**, **1010**, such that readout of the OTP magnetic junctions **104***b* of FIGS. **9**A and **9**B succeeds even at high temperatures (e.g., from reflow).

[0083] The states of broken-down magnetic junctions are unaffected by high temperatures, whereby upper bounds of the first and second OTP read windows **1008**, **1010** can be assumed to be fixed. Further, the states of unbroken-down magnetic junctions may be affected by high temperatures and may hence vary between an anti-parallel state and a parallel state. Therefore, lower bounds of the first and second OTP read windows **1008**, **1010** may vary between the antiparallel read current distribution **1002***a* and the parallel read current distribution **1002***b*. However, even with this variation, the second and third reference currents **1004***b*, **1004***c* still overlap with the first and second OTP read windows **1008**, **1010**, whereby readout may still succeed at high temperatures. Further yet, while high temperatures may vary the locations of the second and third reference currents **1004***b*, **1004***c*, the second and third reference currents **1004***b*, **1004***c* continue to overlap with the first and second OTP read windows **1008**, **1010**, whereby readout may still succeed at high temperatures.

[0084] The locations of the second and third reference currents **1004***b*, **1004***c* are the average of the current through a broken-down reference magnetic junction $M_{r,bd}$ of FIGS. **9**A and **9**B and the current through an anti-parallel or parallel reference magnetic junctions $MJ_{r,ap}$, $MJ_{r,ap}$ of FIGS. **9**A and **9**B. As noted above, the state of a broken-down reference magnetic junction $MJ_{r,bd}$ can be assumed to be fixed, whereby the current through the broken-down reference magnetic junction $MJ_{r,bd}$ can assumed to be fixed. Therefore, it's the current through the anti-parallel or parallel reference magnetic junctions $MJ_{r,ap}$, $MJ_{r,ap}$ that may vary with high temperatures. However, the current varies between the antiparallel read current distribution **1002***a* and the parallel read current distribution **1002***b*, and both current at the antiparallel read current distribution **1002***a* and current at the parallel read current distribution **1002***b* lead to a reference current overlapping with the first and second OTP read windows **1008**, **1010**.

[0085] With reference to FIG. **11**, a block diagram **1100** of some embodiments of a process performed by the integrated chip of FIGS. **9**A and **9**B to read a state of a magnetic junction is provided. The process may, for example, be performed regardless of the whether the magnetic junction is an OTP magnetic junction or an MTP magnetic junction.

[0086] At **1102**, a determination is made as to whether the magnetic junction is OTP or MTP. The determination may, for example, be made based on a provided memory address of the magnetic junction and/or the known locations of an OTP and MTP memory cells.

[0087] At **1104***a*, in response to determine the magnetic junction is MTP, a reference current is generated by averaging a current through a reference magnetic junction in a parallel state and a current through a reference magnetic

junction in an anti-parallel state. The current through the reference magnetic junction in the parallel state may, for example, be generated by applying a read voltage across the reference magnetic junction. Similarly, the current through the reference magnetic junction in the anti-parallel state may, for example, be generated by applying a read voltage across the reference magnetic junction.

[0088] At **1104***b*, in response to determine the magnetic junction is MTP, a reference current is generated by averaging a current through a reference magnetic junction in a parallel or anti-parallel state and a current through a reference magnetic junction in a broken-down state. The current through the reference magnetic junction in the parallel or anti-parallel state may, for example, be generated by applying a read voltage across the reference magnetic junction. Similarly, the current through the reference magnetic junction in the broken-down state may, for example, be generated by applying a read voltage across the reference magnetic junction.

[0089] At **1106**, a determination is made as to whether a read current through the magnetic junction is less than the reference current, regardless of whether the reference current is generated at **1104***a* or **1104***b*. The read current may, for example, be generated by applying a read voltage across the magnetic junction. In response to determining the read current is less than the reference current, the magnetic junction has a first data state (e.g., a logic "0"). In response to determining the read current is greater than the reference current, the magnetic junction has a second data state (e.g., a logic "1").

[0090] While the block diagram **1100** is illustrated and described herein as a series of acts or events, it will be appreciated that the illustrated ordering of such acts or events is not to be interpreted in a limiting sense. For example, some acts may occur in different orders and/or concurrently with other acts or events apart from those illustrated and/or described herein. Further, not all illustrated acts may be required to implement one or more aspects or embodiments of the description herein, and one or more of the acts depicted herein may be carried out in one or more separate acts and/or phases.

[0091] With reference to FIG. **12**A, an expanded top layout **1200**A of some embodiments of the integrated chip of FIGS. **9**A is provided. The expanded top layout **1200**A is expanded in that it illustrates additional rows and columns. For example, the top layout **1200** illustrates columns 1 to M and rows 1 to N, where M and N are integers respectively representing a total number of columns and a total number of rows in the magnetic-junction array **102**.

[0092] The dummy portion **102***c* is at an edge of the magnetic-junction array **102** and extends in a closed path to surround the MTP portion **102***a* of the magnetic-junction array **102**, the OTP portion **102***b* of the magnetic-junction array **102**, and the reference portion **102***d* of the magnetic-junction array **102**. Further, in some embodiments, the dummy portion **102***c* is in the same column (e.g., column C_{M-1}) and the same rows (e.g., rows R_{N-3} to row R_{N-1}) as the reference portion **102***d*. Magnetic junctions at the edge of the magnetic-junction array **102** suffer from non-uniformity due to a large change in feature density at the edge of the magnetic-junction array **102**. The large change causes non-uniformity in processes used to form the magnetic junctions at the edge of the magnetic-junction array **102**, which causes the non-uniformity. Hence, the dummy portion **102***c* serves as a buffer to prevent non-uniformity with magnetic junctions **104** offset from the edge of the magnetic-junction array **102**.

[0093] With reference to FIG. **12**B, a top layout **1200**B of some alternative embodiments of the integrated chip of FIG. **12**A is provided in which the OTP portion **102***b* is at an edge of the magnetic-junction array **102**. The read and write windows for the OTP magnetic junctions **104***b* are relatively large compared to the read and write windows for the MTP magnetic junctions **104***a*. Hence, read and write operations with the OTP magnetic junctions **104***b* can tolerate non-uniformity at the edge of the magnetic-junction array **102**, thereby allowing previously unused magnetic junctions to be used. This, in turn, may increase the functional density of the integrated chip and may reduce manufacturing costs.

[0094] With reference to FIG. **12**C, a top layout **1200**C of some alternative embodiments of the integrated chip of FIG. **12**A is provided in which the OTP portion **102***b* is at an edge of the magnetic-junction array **102** and extends in a closed path to enclose the MTP portion **102***a*, the reference portion **102***d*, and the dummy portion **102***c*. For example, the OTP portion **102***b* may be square-ring shaped or some other suitable shape.

[0095] With reference to FIG. **12**D, a top layout **1200**D of some alternative embodiments of the integrated chip of FIG. **12**A is provided in which the MTP portion **102***a*, the OTP portion **102***b*, and the reference portion **102***d* adjoin the edge of the magnetic-junction array **102**. As such, there are no dummy magnetic junctions within view and out of view at the edge of the magnetic-junction array **102**, except for at the dummy portion **102***c*.

[0096] With reference to FIGS. **13**A-**13**D, top layouts **1300**A-**1300**D of some alternative embodiments of the integrated chip of FIG. **9**B is provided. FIGS. **13**A-**13**D are respectively variants of FIGS. **12**A-**12**D in which the layout of FIG. **9**A is used in place of the layout of FIG. **9**B. For example, FIG. **13**A is a variant of FIG. **12**A in which the layout of FIG. **9**A has been replaced by the layout of FIG. **9**B.

[0097] With reference to FIG. **14**A, a schematic diagram **1400**A of some embodiments an integrated chip comprising a memory array **502** with the magnetic-junction array **102** of FIG. **12**A is provided. The memory array **502** comprises multiple memory cells **504** distributed amongst an MTP portion **502***a*, an OTP portion **502***b*, a dummy portion **502***c*, and a reference portion **502***d*. For ease of illustration, only some of the memory cells **504** are labeled **504**. The memory cells **504** are in M columns and N rows, where M and N are integers respectively represent a total number of columns and a total number of rows. The memory cells **504** comprise individual access transistors **506** and individual magnetic junctions **104**. For ease of illustration, only some of the access transistors **506** are labeled **506** and only some of the magnetic junctions **104** are labeled **104**.

[0098] Memory cells **504***a* in the MTP portion **502***a* (i.e., MTP memory cells **504***a*) each store a bit of data, the state of which varies depending upon magnetizations of an individual magnetic junction MJ_{mt}. For ease of illustration, only one of the MTP memory cells **504***a* is individually labeled **504***a*. Memory cells **504***b* in the OTP portion **502***b* (i.e., OTP memory cells **504***b*) each store a bit of data, the state of which varies depending upon whether an individual magnetic junction MJ_{ot} has undergone breakdown. For ease of illustration, only one of the OTP memory cells **504***b* is

individually labeled **504***b*. Memory cells **504***c* in the dummy portion **502***c* (i.e., dummy memory cells **504***c*) are unused and typically have poor uniformity compared to the MTP and OTP memory cells **504***a*, **504***b*. In some embodiments, the dummy memory cells **504***c* have magnetic junctions and access transistors that are electrically separated, as denoted by gaps **702**. For ease of illustration, only one of the dummy memory cells **504***c* is labeled **504***c* and only one of the gaps **702** is labeled **702**. Memory cells **504***d* in the reference portion **502***d* (i.e., reference memory cells **504***d*) correspond to the different states of the MTP and OTP memory cells **504***a*, **504***b* and are used to generate a reference current I_{ref} during readout (discussed hereafter) of one of the MTP and OTP memory cells **504***a*, **504***b*. For ease of illustration, only one of the reference memory cells **504***d* is labeled **504***d*.

[0099] In some embodiments, the memory cells **504** share a common size, regardless of whether in the MTP portion **502***a*, the OTP portion **502***b*, the dummy portion **502***c*, or the reference portion **502***d*. In some embodiments, a row-wise pitch P_r of the memory array **502** is uniform throughout the memory array **502**, regardless of whether at and/or between the MTP portion **502***a*, the OTP portion **502***b*, the dummy portion **502***c*, and the reference portion **502***d*. Similarly, in some embodiments, a column-wise pitch P_c of the memory array **502** is uniform throughout the memory array **502**, regardless of whether at and/or between the MTP portion **502***a*, the OTP portion **502***b*, the dummy portion **502***c*, or the reference portion **502***d*. The row-wise pitch P_r may, for example, be 260 nanometers or less, and/or the column-wise pitch P_c may, for example, be 220 nanometers or less, or vice versa. Other values for the row-wise pitch P_r and/or the column-wise pitch P_c are, however, amenable.

[0100] A set of word lines **508** and a row decoder/driver **1402** facilitate selection of the memory cells **504** on a row-by-row basis. For ease of illustration, only some of the word lines **508** are labeled **508**. The word lines **508** extend laterally along corresponding rows of the memory array **502** and electrically couple with gates of access transistors in the corresponding rows. The row decoder/driver **1402** selects a row via the word lines **508** depending upon a memory address (not shown). For example, the row decoder/driver **1402** may select a row of the memory address by biasing a word line at the row with a voltage in excess of a threshold voltage of the access transistors **506**. Further, in some embodiments, the row decoder/driver **1402** selects rows of the reference portion **502***d* during read operations. For example, the row decoder/driver **1402** may select row R_{N-3} and row R_{N-2}, but not row R_{N-1}, during a read operation for an MTP memory cell. As another example, the row decoder/driver **1402** may select row R_{N-1} and row R_{N-3}, but not row R_{N-2}, during a read operation for an OTP memory cell. As yet another example, the row decoder/driver **1402** may select row R_{N-1} and row R_{N-2}, but not row R_{N-3}, during a read operation for an OTP memory cell.

[0101] A set of bit lines **510**, a set of source lines **512**, and a column decoder/driver **1404** facilitate reading from and/or writing to selected memory cells on a column-by-column basis. The bit lines **510** extend laterally along corresponding columns of the memory array **502** and electrically couple with magnetic junctions in the corresponding columns. The source lines **512** extend laterally along corresponding columns of the memory array **502** and electrically couple with sources of access transistors in the corresponding columns.

[0102] To write to a selected memory cell, the column decoder/driver **1404** applies a write voltage across the selected memory cell with a bit line in a column of the selected memory cell and a source line in the column. To read from a selected memory cell, the column decoder/driver **1404** applies a read voltage to a terminal of the selected memory cell with one of the bit and source lines in a column of the selected memory cell. A read current I_{read} at the other one of the bit and source lines in the column is then fed to a sense amplifier **902**, where it is compared to a reference current I_{ref} to determine a data state of the selected memory cell.

[0103] A reference circuit **1406** generates the reference current I_{ref} from the reference memory cells **504***d*. For example, assuming the row decoder/driver **1402** appropriately selects two rows of the reference portion **502***d*, as described above, applying a read voltage to one of the bit and source lines in column C_{M-1} results in a composite current at the other one of the bit and source lines in column C_{M-1}. The composite current is the sum of the currents flowing through the selected reference memory cells, whereby the reference current I_{ref} may be generated by the reference circuit **1406** halving the composite current. In some embodiments, the reference circuit **1406** is part of the column decoder/driver **1404**. In other embodiments, the reference circuit **1406** is independent of the column decoder/driver **1404**.

[0104] With reference to FIG. **14**B, a schematic diagram **1400**B of some embodiments an integrated chip comprising a memory array **502** with the magnetic-junction array **102** of FIG. **13**A is provided. FIG. **14**B may, for example, be regarded as a variant of FIG. **14**A in which the magnetic-junction array **102** of FIG. **13**A is used in placed of the magnetic-junction array **102** of FIG. **12**A, whereby FIG. **14**B may, for example, be as FIG. **14**A is described except as it pertains to generation of the reference current I_{ref}.

[0105] Since each of the rows has a complete set of reference cells (i.e., one reference cell for each state of the MTP and OTP memory cells **504***a*, **504***b*), the row decoder **1402** selects a complete set of reference cells when it selects a row of memory cells for readout. Further, during readout, the column decoder/driver **1404** biases bit lines for two of the selected reference cells depending upon a type of memory cell being read. For example, the column decoder/driver **1404** may select column C_{M-3} and column C_{M-2}, but not column C_{M-1}, during readout of an MTP memory cell. As another example, the column decoder/driver **1404** may select column C_{M-1} and column C_{M-3}, but not column C_{M-2}, during readout of an OTP memory cell. As yet another example, the column decoder/driver **1404** may select column C_{M-1} and column C_{N-2}, but not column C_{M-3}, during readout of an OTP memory cell. Biasing the bit lines for the two selected reference cells results in read currents at corresponding source lines. The reference circuit **1406** then averages the read currents to generate the reference current I_{ref}.

[0106] While FIG. **14**A is illustrated with embodiments of the magnetic-junction array **102** in FIG. **12**A, embodiments of the magnetic-junction array **102** in any one of FIGS. **12**B-**12**D may be alternatively used. While FIG. **14**B is illustrated with embodiments of the magnetic-junction array **102** in FIG. **13**A, embodiments of the magnetic-junction array **102** in any one of FIGS. **13**B-**13**D may be alternatively used.

[0107] With reference to FIGS. **15-19**, a series of cross-sectional views **1500-1900** of some embodiments of a method for forming an integrated chip comprising a memory array **502** with an MTP portion **502***a*, an OTP portion **502***b*, a dummy portion **502***c*, and a reference portion **502***d* is provided. For ease of illustration, only one memory cell is illustrated in each of the portions. In practice, however, there will be multiple memory cells in each of the portions. Further, it should be appreciated that the relative positioning of the portions is for illustrative purposes and should not be construed as limiting. Multiple examples of the relative positioning of the portions are described above. See, for example, FIGS. **12**A-**12**D and FIGS. **13**A-**13**D.

[0108] As illustrated by the cross-sectional view **1500** of FIG. **15**, access transistors **506** are formed on a substrate **802**, respectively at the MTP portion **502***a*, the OTP portion **502***b*, the dummy portion **502***c*, and the reference portion **502***d*. For ease of illustration, only some of the illustrated segments of the substrate **802** are labeled **802**. Although not visible within the cross-sectional view **1500** of FIG. **15**, the access transistors **506** may, for example, be formed in a plurality of rows and a plurality of columns when viewed top down so as to define an access-transistor array. The access transistors **506** may, for example, have a uniform size throughout the access-transistor array and/or the access-transistor array may, for example, have a uniform row-wise pitch and/or a uniform column-wise pitch throughout the access-transistor array.

[0109] The access transistors **506** comprise individual pairs of source/drain regions **804**, individual gate dielectric layers **806**, and individual gate electrodes **808**. For ease of illustration, only some of the source/drain regions **804** are labeled **804**, only some of the gate dielectric layers **806** are labeled **806**, and only some of the gate electrodes **808** are labeled **808**. The source/drain regions **804** are in the substrate **802** and have an opposite doping type as adjoining portions of the substrate **802**. The gate dielectric layers **806** overlie the substrate **802** and are each sandwiched between two of the source/drain regions **804**. The gate electrodes **808** respectively overlie the gate dielectric layers **806**. The access transistors **506** may, for example, be MOSFETs, IGFETs, or some other suitable transistors.

[0110] In some embodiments, a process for forming the access transistors **506** comprises: 1) depositing a dielectric layer on the substrate **802**; 2) depositing a conductive layer on the dielectric layer; 3) patterning the dielectric layer and the conductive layer respectively into the gate dielectric layers **806** and the gate electrodes **808**; and 4) implanting dopants into the substrate **802** to form the source/drain regions **804**. Other processes for forming the access transistors **506** are, however, amenable. The depositing of the dielectric layer may, for example, be performed by chemical vapor deposition (CVD), physical vapor deposition (PVD), thermal oxidation, some other suitable deposition process (es), or any combination of the foregoing. The depositing of the conductive layer may, for example, be performed by CVD, PVD, electroless plating, electroplating, some other suitable deposition process(es), or any combination of the foregoing. The patterning may, for example, be performed by a photolithography/etching process and/or some other suitable patterning process(es). The implanting may, for example, be performed by ion implantation and/or some other suitable implantation process(es).

[0111] As illustrated by the cross-sectional view **1600** of FIG. **16**, an interconnect structure **1602** is partially formed over the substrate **802** and the access transistors **506**. The interconnect structure **1602** comprises a lower interconnect dielectric layer **1604**, multiple wires **810**, and multiple vias **812**. For ease of illustration, only some of the wires **810** are labeled **810** and only some of the vias **812** are labeled **812**. Further, only some of the illustrated segments of the lower interconnect dielectric layer **1604** are labeled **1604**.

[0112] The lower interconnect dielectric layer **1604** accommodates the wires **810** and the vias **812** and may, for example, be or comprise silicon oxide, a low κ dielectric, some other suitable dielectric(s), or any combination of the foregoing. As used herein, a low κ dielectric may be, for example, a dielectric with a dielectric constant κ less than about 3.9, 3, 2, or 1. The wires **810** and the vias **812** are alternatingly stacked in the lower interconnect dielectric layer **1604** to define conductive paths leading from the access transistors **506**. Further, the wires **810** and the vias **812** have the same layout at the MTP portion **502***a*, the OTP portion **502***b*, the dummy portion **502***c*, and the reference portion **502***d*, except that, in some (not all) embodiments, a via is missing at the dummy portion **502***c* (denoted by a dashed oval **1606**). As seen hereafter, the missing via renders the memory cell at the dummy portion **502***c* non-functional.

[0113] The wires **810** and the vias **812** define first conductive paths from first source/drain regions to individual source lines **512**, and further define second conductive paths from the gate electrodes **808** to individual word lines **508**. For ease of illustration, only some of the word lines **508** are labeled **508** and only some of the source lines **512** are labeled **512**. Further, the wires **810** and the vias **812** define third conductive paths from second source/drain regions to a top of the lower interconnect dielectric layer **1604**. In some embodiments, a third conductive path at the dummy portion **502***c* is discontinuous due to a missing via (denoted by the dashed oval **1606**). In other embodiments, the third conductive path at the dummy portion **502***c* is continuous.

[0114] In some embodiments, a process for partially forming the interconnect structure **1602** comprises: 1) forming a bottommost layer of the vias **812** by a single damascene process; 2) forming a bottommost layer of the wires **810** by the single damascene process; 3) forming wires and vias over the bottommost layer of the wires **810** by repeatedly performing a dual damascene process; and 4) forming bottom electrode vias (BEVAs) of the vias **812** by a single damascene process. Other processes for partially forming the interconnect structure **1602** are, however, amenable. In some embodiments, the single damascene process comprises: 1) depositing a dielectric layer; 2) patterning the dielectric layer with openings for a single layer of conductive features (e.g., a layer of vias or a layer of wires); 3) and filling the openings with conductive material to form the single layer of conductive features. In some embodiments, the dual damascene process comprises: 1) depositing a dielectric layer; 2) patterning the dielectric layer with openings for two layers of conductive features (e.g., a layer of vias and a layer of wires); 3) and filling the openings with conductive material to form the two layers of conductive features. In both the single and dual damascene processes, the dielectric layer is a portion of the lower interconnect dielectric layer **1604**.

[0115] As illustrated by the cross-sectional view **1700** of FIG. **17**, magnetic junctions **104** are formed on the inter-

connect structure **1602**, respectively at the MTP portion **502***a*, the OTP portion **502***b*, the dummy portion **502***c*, and the reference portion **502***d*. Further, the magnetic junctions **104** are formed respectively on topmost vias. Although not visible within the cross-sectional view **1700** of FIG. **17**, the magnetic junctions **104** may, for example, be formed in a plurality of rows and a plurality of columns when viewed top down so as to define a magnetic-junction array. The magnetic junctions **104** may, for example, have a uniform size throughout the magnetic-junction array and/or the magnetic-junction array may, for example, have a uniform row-wise pitch and/or a uniform column-wise pitch throughout the access-transistor. Examples of the magnetic-junction array are in FIGS. **1**, **4**A-**4**C, **9**A, **9**B, **12**A-**12**D and **13**A-**13**D. The magnetic junctions **104** comprise individual reference elements **204**, individual barrier elements **208**, and individual free elements **206**. In some embodiments, the barrier elements **208** respectively overlie the reference elements **204**, and the free elements **206** respectively overlie the barrier elements **208**. In other embodiments, the barrier elements **208** respectively overlie the free elements **206**, and the reference elements **204** respectively overlie the barrier elements **208**. The magnetic junctions **104** may, for example, be MTJs, spin valves, or some other suitable magnetic junctions. Further, the magnetic junctions **104** may, for example, each be as the unbroken-down magnetic junction **302** of FIG. **3** is described.

[0116] In some embodiments, a process for forming the magnetic junctions **104** comprises: 1) depositing a reference layer on the interconnect structure **1602**; 2) depositing a barrier layer on the reference layer; 3) depositing a free layer on the barrier layer; and 4) patterning the reference, barrier, and free layers into the magnetic junctions **104**. Other processes are, however, amenable. For example, the free layer may be deposited at 1) and the reference layer may be deposited at 3). The depositing may, for example, be performed by CVD, PVD, electroless plating, electroplating, some other suitable deposition process(es), or any combination of the foregoing. The patterning may, for example, be performed by a photolithography/etching process and/or some other suitable patterning process(es).

[0117] As illustrated by the cross-sectional view **1800** of FIG. **18**, the interconnect structure **1602** is completed around the magnetic junctions **104**, whereby an upper interconnect dielectric layer **1802** is formed over the magnetic junctions **104**. Further, additional wires **810** and additional vias **812** are formed in the upper interconnect dielectric layer **1802**. For ease of illustration, only some of the additional wires **810** are labeled **810** and only some of the additional vias **812** are labeled **812**. Further, only some of the illustrated segments of the upper interconnect dielectric layer **1802** are labeled **1802**.

[0118] The upper interconnect dielectric layer **1802** accommodates the additional wires **810** and the additional vias **812** and may, for example, be or comprise silicon oxide, a low κ dielectric, some other suitable dielectric(s), or any combination of the foregoing. The additional wires **810** and the additional vias **812** are alternatingly stacked in the upper interconnect dielectric layer **1802** to define conductive paths leading from the magnetic junctions **104** to bit lines **510**. For ease of illustration, only one of the bit lines **510** is labeled **510**. Further, the additional wires **810** and the additional vias **812** have the same layout at the MTP portion **502***a*, the OTP portion **502***b*, the dummy portion **502***c*, and the reference portion **502***d*.

[0119] In some embodiments, a process for completing the interconnect structure **1602** comprises: 1) forming top electrode vias (TEVAs) of the additional vias **812** by a single damascene process; 2) forming additional wires and additional vias over the TEVAs by repeatedly performing a dual damascene process; and 3) depositing a passivation layer over the additional wires and the additional vias. Other processes for completing the interconnect structure **1602** are, however, amenable. The single and dual damascene processes may, for example, be performed as described with regard to FIG. **16**.

[0120] As illustrated by the cross-sectional view **1900** of FIG. **19**, the magnetic junction at the OTP portion **502***b* is broken down to form defects **210** in the barrier element **208**. The defects may, for example, be or comprise a conductive filament or some other suitable defects. In some embodiments, break down is performed by applying a high voltage across the magnetic junction at the OTP portion **502***b*. In some embodiments, the breakdown voltage causes hard breakdown and/or irreversible breakdown of the barrier element **208**, such that the broken-down state of the barrier element **208** is not affected by high temperatures, such as those temperatures during reflow processes. In some embodiments, other memory cells (not shown) at the OTP portion **502***b* are not broken down and are hence left in an unbroken-down state.

[0121] The method illustrated by FIGS. **15-19** may, for example, be employed to form the integrated chip in any one of FIGS. **1**, **4**A-**4**C, **5**, **6**A, **6**B, **7**, **9**A, **9**B, **12**A-**12**D, **13**A-**13**D, **14**A, and **14**B. While the cross-sectional views **1500-1900** shown in FIGS. **15-19** are described with reference to the method, it will be appreciated that the structures shown in FIGS. **15-19** are not limited to the method and may stand alone without the method.

[0122] With reference to FIG. **20**, a block diagram **2000** of some embodiments of the method of FIGS. **15-19** is provided.

[0123] At **2002**, access transistors are formed on a substrate, respectively at an MTP portion, an OTP portion, a dummy portion, and a reference portion. See, for example, FIG. **15**.

[0124] At **2004**, an interconnect structure is partially formed over the access transistors and the substrate. See, for example, FIG. **16**.

[0125] At **2006**, magnetic junctions are formed on the interconnect structure, respectively at the MTP portion, the OTP portion, the dummy portion, and the reference portion. See, for example, FIG. **17**.

[0126] At **2008**, the interconnect structure is completed around the magnetic junctions. See, for example, FIG. **18**.

[0127] At **2010**, a breakdown voltage is applied to a magnetic junction at the OTP portion to breakdown a barrier element of the magnetic junction. See, for example, FIG. **19**.

[0128] While the block diagram **2000** of FIG. **20** is illustrated and described herein as a series of acts or events, it will be appreciated that the illustrated ordering of such acts or events is not to be interpreted in a limiting sense. For example, some acts may occur in different orders and/or concurrently with other acts or events apart from those illustrated and/or described herein. Further, not all illustrated acts may be required to implement one or more aspects or

embodiments of the description herein, and one or more of the acts depicted herein may be carried out in one or more separate acts and/or phases.

[0129] In some embodiments, the present application provides an integrated chip including: an array including a plurality of magnetic junctions in a plurality of columns and a plurality of rows, wherein the plurality of magnetic junctions includes a first magnetic junction and a second magnetic junction, and wherein the first and second magnetic junctions include individual top ferromagnetic elements and individual bottom ferromagnetic elements, and further include individual barrier elements between the top and bottom ferromagnetic elements; wherein a first barrier element of the first magnetic junction electrically separates first top and bottom ferromagnetic elements of the first magnetic junction, and wherein a second barrier element of the second magnetic junction includes defects defining a leakage path between second top and bottom ferromagnetic elements of the second magnetic junction. In some embodiments, the first magnetic junction is offset from an edge of the array and the second magnetic junction is at an edge of the array. In some embodiments, the integrated chip further includes: an access transistor having a first source/drain electrically coupled to a second bottom ferromagnetic element of the second magnetic junction; and a pair of conductive lines extending along a column of the array in which the second magnetic junction is located, wherein the conductive lines are respectively and electrically coupled to a second source/drain of the access transistor and a second top ferromagnetic element of the second magnetic junction. In some embodiments, the integrated chip further includes a second access transistor electrically coupled in parallel with the access transistor. In some embodiments, the first and second magnetic junctions have the same width. In some embodiments, the first barrier element of the first magnetic junction has a top surface that is flat, wherein the second barrier element of the second magnetic junction has a top surface that is curved. In some embodiments, the plurality of magnetic junctions includes a third magnetic junction in the same column of the array as the second magnetic junction, wherein the integrated chip further includes an access transistor directly under the third magnetic junction and electrically separated from the third magnetic junction. In some embodiments, the plurality of magnetic junctions further includes a third magnetic junction, wherein the integrated chip further includes: a reference circuit configured to generate a reference current by averaging individual currents flowing across the first and second magnetic junctions; and a sense amplifier configured to compare the reference current to a read current flowing across the third magnetic junction. In some embodiments, the third magnetic junction includes a third top ferromagnetic element and a third bottom ferromagnetic element, and further includes a third barrier element between the third top and bottom ferromagnetic elements, wherein the third top ferromagnetic element includes defects defining a leakage path between the third top and bottom ferromagnetic elements. In some embodiments, the third magnetic junction includes a third top ferromagnetic element and a third bottom ferromagnetic element, and further includes a third barrier element between the third top and bottom ferromagnetic elements, wherein the third top ferromagnetic element electrically separates the third top and bottom ferromagnetic elements.

[0130] In some embodiments, the present application provides a method for forming an integrated chip, the method including: forming an array including multiple magnetic junctions in a plurality of rows and a plurality of columns, wherein the magnetic junctions include individual top ferromagnetic elements and individual bottom ferromagnetic elements, and further include individual barrier elements separating the top and bottom ferromagnetic elements; and applying a breakdown voltage individually across first magnetic junctions in a first portion of the array, but not a second portion of the array, wherein the breakdown voltage damages barrier elements of the first magnetic junctions to define leakage paths between top and bottom ferromagnetic elements of the first magnetic junctions. In some embodiments, the applying is performed at temperatures in excess of about 100 degrees Celsius. In some embodiments, the forming of the array includes: depositing a bottom ferromagnetic layer; depositing a barrier layer on the bottom ferromagnetic layer; depositing a top ferromagnetic layer on the barrier layer; and patterning the bottom ferromagnetic layer, the barrier layer, and the top ferromagnetic layer into the array. In some embodiments, the first portion of the array is at an edge of the array and the second portion of the array is fully offset from each edge of the array.

[0131] In some embodiments, the present application provides a method for reading a memory array, the method including: providing an array including multiple magnetic junctions in a plurality of rows and a plurality of columns, wherein the magnetic junctions include individual top ferromagnetic elements and individual bottom ferromagnetic elements, and further include individual barrier elements between the top and bottom ferromagnetic elements; generating a reference current by averaging a first current through a first magnetic junction of the array and a second current through a second magnetic junction of the array; and comparing a read current through a third magnetic junction in the array to the reference current to sense a state of the third magnetic junction, wherein a barrier element of the first magnetic junction electrically separates top and bottom ferromagnetic elements of the first magnetic junction, and wherein a barrier element of the second magnetic junction includes defects defining a leakage path between top and bottom ferromagnetic elements of the second magnetic junction. In some embodiments, the top and bottom ferromagnetic elements of the first magnetic junction have parallel magnetizations. In some embodiments, the top and bottom ferromagnetic elements of the first magnetic junction have anti-parallel magnetizations. In some embodiments, a barrier element of the third magnetic junction electrically separates top and bottom ferromagnetic elements of the third magnetic junction. In some embodiments, a barrier element of the third magnetic junction includes defects defining a leakage path between top and bottom ferromagnetic elements of the third magnetic junction. In some embodiments, the method further includes: biasing a word line extending along a row of the array to select the row, wherein the second magnetic junction is in the row; and biasing a bit line extending along a column of the array to generate the second current at a source line extending along the column, wherein the second magnetic junction is in the column.

[0132] The foregoing outlines features of several embodiments so that those skilled in the art may better understand the aspects of the present disclosure. Those skilled in the art should appreciate that they may readily use the present

disclosure as a basis for designing or modifying other processes and structures for carrying out the same purposes and/or achieving the same advantages of the embodiments introduced herein. Those skilled in the art should also realize that such equivalent constructions do not depart from the spirit and scope of the present disclosure, and that they may make various changes, substitutions, and alterations herein without departing from the spirit and scope of the present disclosure.

1. An integrated chip comprising:

an array comprising a plurality of magnetic junctions in a plurality of columns and a plurality of rows, wherein the plurality of magnetic junctions comprises a first magnetic junction and a second magnetic junction, and wherein the first and second magnetic junctions comprise individual top ferromagnetic elements and individual bottom ferromagnetic elements, and further comprise individual barrier elements between the top and bottom ferromagnetic elements;

wherein a first barrier element of the first magnetic junction electrically separates first top and bottom ferromagnetic elements of the first magnetic junction, and wherein a second barrier element of the second magnetic junction comprises defects defining a leakage path between second top and bottom ferromagnetic elements of the second magnetic junction.

2. The integrated chip according to claim **1**, wherein the first magnetic junction is offset from an edge of the array and the second magnetic junction is at an edge of the array.

3. The integrated chip according to claim **1**, further comprising:

an access transistor having a first source/drain electrically coupled to the second bottom ferromagnetic element of the second magnetic junction; and

a pair of conductive lines extending along a column of the array in which the second magnetic junction is located, wherein the conductive lines are respectively and electrically coupled to a second source/drain of the access transistor and the second top ferromagnetic element of the second magnetic junction.

4. The integrated chip according to claim **3**, further comprising:

a second access transistor electrically coupled in parallel with the access transistor.

5. The integrated chip according to claim **1**, wherein the first and second magnetic junctions have the same width.

6. The integrated chip according to claim **1**, wherein the first barrier element of the first magnetic junction has a top surface that is flat, and wherein the second barrier element of the second magnetic junction has a top surface that is curved.

7. The integrated chip according to claim **1**, wherein the plurality of magnetic junctions comprises a third magnetic junction in the same column of the array as the second magnetic junction, and wherein the integrated chip further comprises:

an access transistor directly under the third magnetic junction and electrically separated from the third magnetic junction.

8. The integrated chip according to claim **1**, wherein the plurality of magnetic junctions further comprises a third magnetic junction, and wherein the integrated chip further comprises:

a reference circuit configured to generate a reference current by averaging individual currents flowing across the first and second magnetic junctions; and

a sense amplifier configured to compare the reference current to a read current flowing across the third magnetic junction.

9. The integrated chip according to claim **8**, wherein the third magnetic junction comprises a third top ferromagnetic element and a third bottom ferromagnetic element, and further comprises a third barrier element between the third top and bottom ferromagnetic elements, and wherein the third top ferromagnetic element comprises defects defining a leakage path between the third top and bottom ferromagnetic elements.

10. The integrated chip according to claim **8**, wherein the third magnetic junction comprises a third top ferromagnetic element and a third bottom ferromagnetic element, and further comprises a third barrier element between the third top and bottom ferromagnetic elements, and wherein the third barrier element electrically separates the third top and bottom ferromagnetic elements.

11. A method for forming an integrated chip, the method comprising:

forming an array comprising multiple magnetic junctions in a plurality of rows and a plurality of columns, wherein the magnetic junctions comprise individual top ferromagnetic elements and individual bottom ferromagnetic elements, and further comprise individual barrier elements separating the top and bottom ferromagnetic elements; and

applying a breakdown voltage individually across first magnetic junctions in a first portion of the array, but not a second portion of the array, wherein the breakdown voltage damages barrier elements of the first magnetic junctions to define leakage paths between top and bottom ferromagnetic elements of the first magnetic junctions.

12. The method according to claim **11**, wherein the applying is performed at temperatures in excess of about 100 degrees Celsius.

13. The method according to claim **11**, wherein the forming of the array comprises:

depositing a bottom ferromagnetic layer;

depositing a barrier layer on the bottom ferromagnetic layer;

depositing a top ferromagnetic layer on the barrier layer; and

patterning the bottom ferromagnetic layer, the barrier layer, and the top ferromagnetic layer into the array.

14. The method according to claim **11**, wherein the first portion of the array is at an edge of the array and the second portion of the array is fully offset from each edge of the array.

15. A method for reading a memory array, the method comprising:

providing an array comprising multiple magnetic junctions in a plurality of rows and a plurality of columns, wherein the magnetic junctions comprise individual top ferromagnetic elements and individual bottom ferromagnetic elements, and further comprise individual barrier elements between the top and bottom ferromagnetic elements;

generating a reference current by averaging a first current through a first magnetic junction of the array and a second current through a second magnetic junction of the array; and

comparing a read current through a third magnetic junction in the array to the reference current to sense a state of the third magnetic junction,

wherein a barrier element of the first magnetic junction electrically separates top and bottom ferromagnetic elements of the first magnetic junction, and wherein a barrier element of the second magnetic junction comprises defects defining a leakage path between top and bottom ferromagnetic elements of the second magnetic junction.

16. The method according to claim **15**, wherein the top and bottom ferromagnetic elements of the first magnetic junction have parallel magnetizations.

17. The method according to claim **15**, wherein the top and bottom ferromagnetic elements of the first magnetic junction have anti-parallel magnetizations.

18. The method according to claim **15**, wherein a barrier element of the third magnetic junction electrically separates top and bottom ferromagnetic elements of the third magnetic junction.

19. The method according to claim **15**, wherein a barrier element of the third magnetic junction comprises defects defining a leakage path between top and bottom ferromagnetic elements of the third magnetic junction.

20. The method according to claim **15**, further comprising:

biasing a word line extending along a row of the array to select the row, wherein the second magnetic junction is in the row; and

biasing a bit line extending along a column of the array to generate the second current at a source line extending along the column, wherein the second magnetic junction is in the column.

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